



US00D947160S

(12) **United States Design Patent**
Chong

(10) **Patent No.:** **US D947,160 S**
(45) **Date of Patent:** **** Mar. 29, 2022**

(54) **HEADPHONE STAND**

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Singapore (SG)

(72) Inventor: **Boon Sim Chong**, Singapore (SG)

(73) Assignee: **RAZER (ASIA-PACIFIC) PTE. LTD.**,
Singapore (SG)

(**) Term: **15 Years**

(21) Appl. No.: **29/750,836**

(22) Filed: **Sep. 16, 2020**

(51) **LOC (13) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/224**

(58) **Field of Classification Search**
USPC D14/224-229; D16/244; D17/99;
D6/672, 681, 682, 526; 248/125.1, 166,
(Continued)

(56) **References Cited**

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(Continued)

Primary Examiner — Katie Jane Stofko
(74) *Attorney, Agent, or Firm* — Polsinelli PC

(57) **CLAIM**

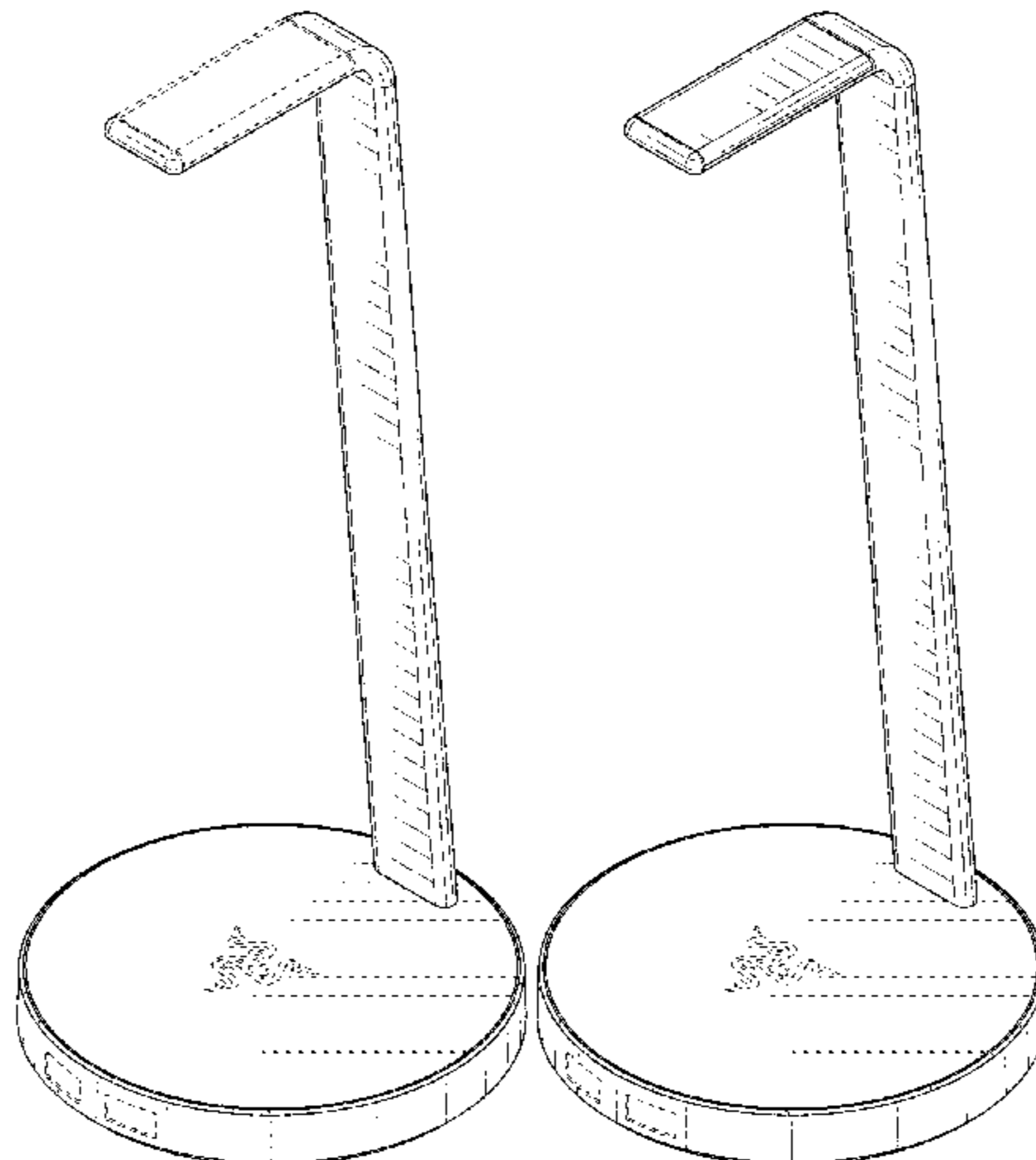
I claim the ornamental design for a headphone stand, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a first embodiment of a headphone stand, showing my new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left side elevational view thereof;

FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof;
FIG. 8 is a perspective view of a second embodiment of the headphone stand;
FIG. 9 is a front elevational view thereof;
FIG. 10 is a rear elevational view thereof;
FIG. 11 is a left side elevational thereof;
FIG. 12 is a right side elevational view thereof;
FIG. 13 is a top plan view thereof;
FIG. 14 is a bottom plan view thereof;
FIG. 15 is a perspective view of a third embodiment of the headphone stand;
FIG. 16 is a front elevational view thereof;
FIG. 17 is a rear elevational view thereof;
FIG. 18 is a left side elevational view thereof;
FIG. 19 is a right side elevational view thereof;
FIG. 20 is a top plan view thereof;
FIG. 21 is a bottom plan view thereof;
FIG. 22 is a perspective view of a fourth embodiment of the headphone stand;
FIG. 23 is a front elevational view thereof;
FIG. 24 is a rear elevational view thereof;
FIG. 25 is a left side elevational view thereof;
FIG. 26 is a right side elevational view thereof;
FIG. 27 is a top plan view thereof;
FIG. 28 is a bottom plan view thereof;
FIG. 29 is a perspective view of a fifth embodiment of the headphone stand;
FIG. 30 is a front elevational view thereof;
FIG. 31 is a rear elevational view thereof;
FIG. 32 is a left side elevational view thereof;
FIG. 33 is a right side elevational view thereof;
FIG. 34 is a top plan view thereof;
FIG. 35 is a bottom plan view thereof;
FIG. 36 is a perspective view of a sixth embodiment of the headphone stand;
FIG. 37 is a front elevational view thereof;
FIG. 38 is a rear elevational view thereof;
FIG. 39 is a left side elevational view thereof;
FIG. 40 is a right side elevational view thereof;
FIG. 41 is a top plan view thereof; and,
FIG. 42 is a bottom plan view thereof.

(Continued)



The broken lines are for illustrating portions of the head-
phone stand, which form no part of the claimed design.
The stippling type represents a contrast in appearance as
shown.

1 Claim, 24 Drawing Sheets

(58) **Field of Classification Search**

USPC 248/185.1; 381/355, 359, 361-363, 365,
381/366, 369, 375; 379/428.01, 428.04,
379/431, 433.03

CPC . H04R 25/00; H04R 1/02; H04R 5/02; H04R
9/08; F16M 11/38; F16M 13/00; F16M
11/00

See application file for complete search history.

(56)

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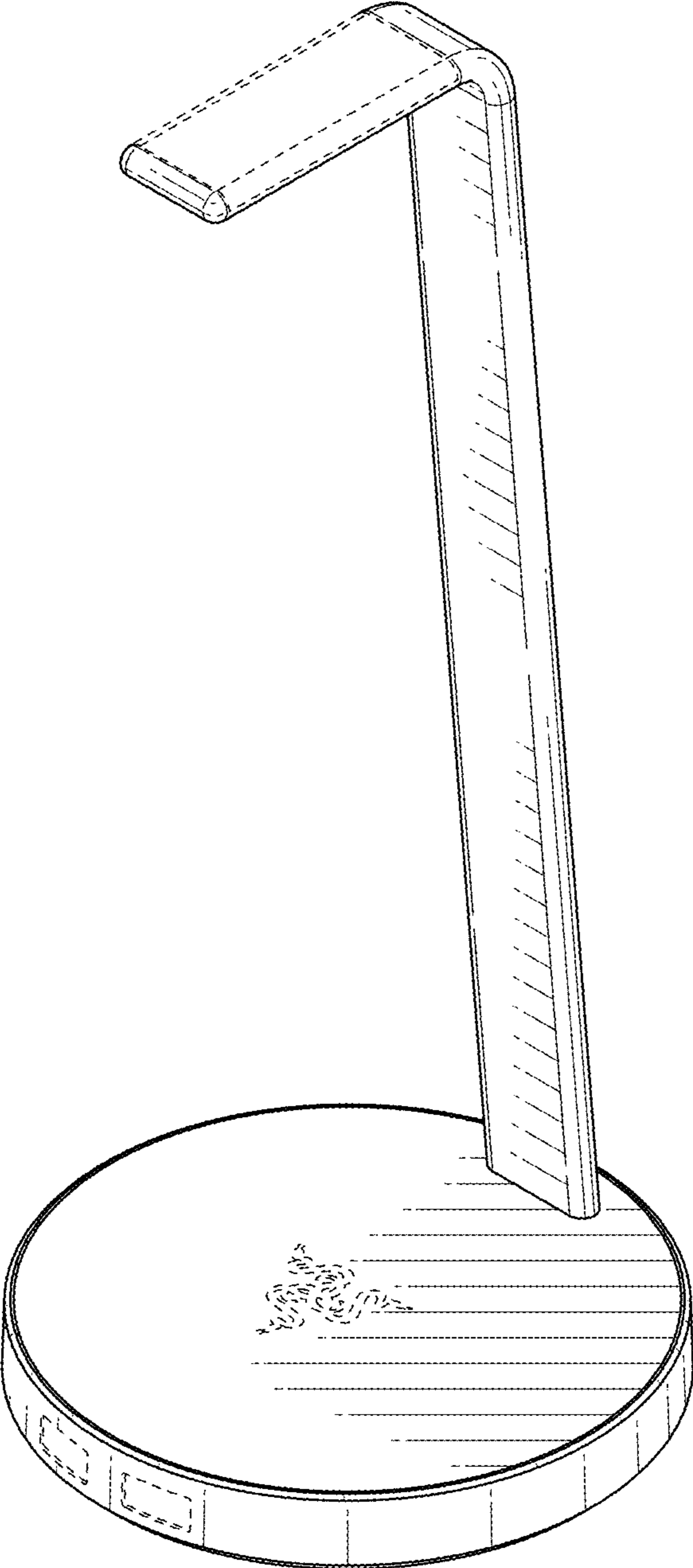


FIG. 1

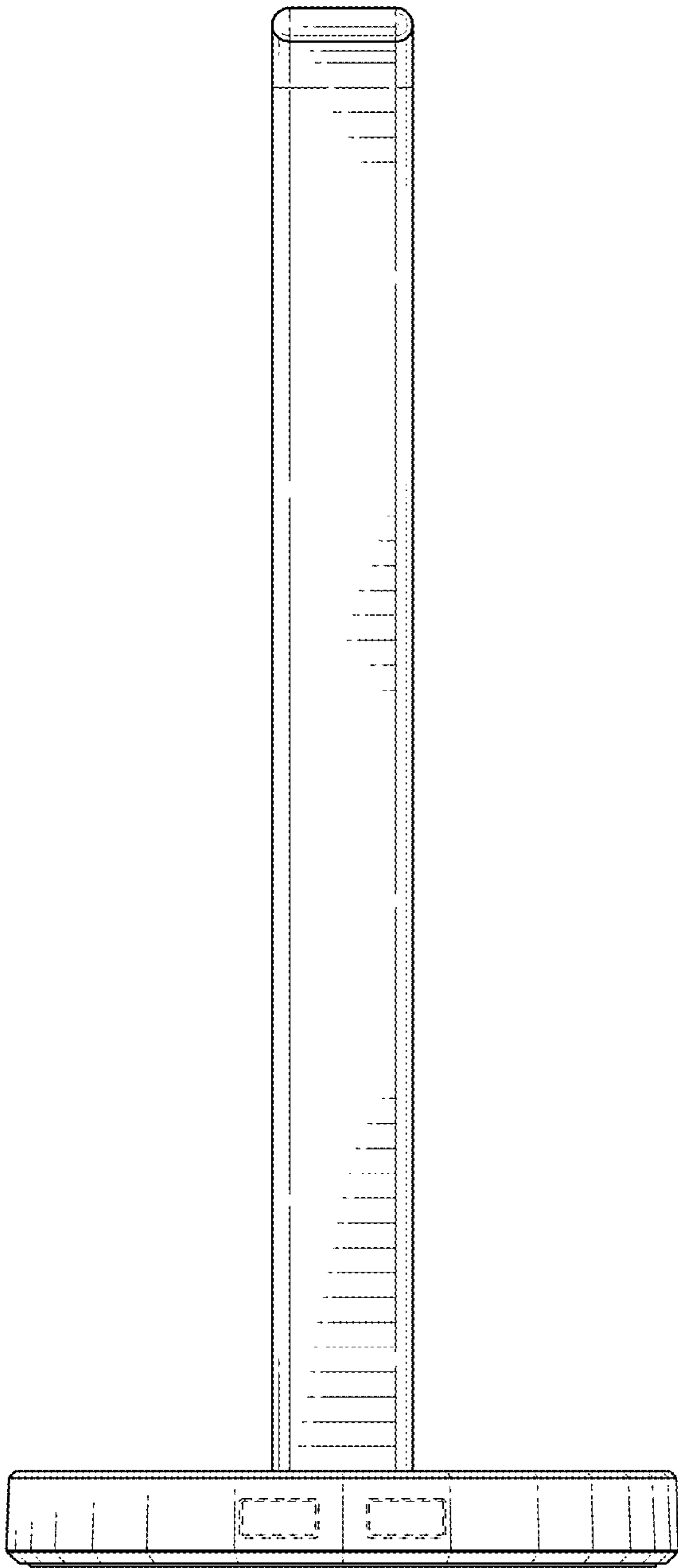


FIG. 2

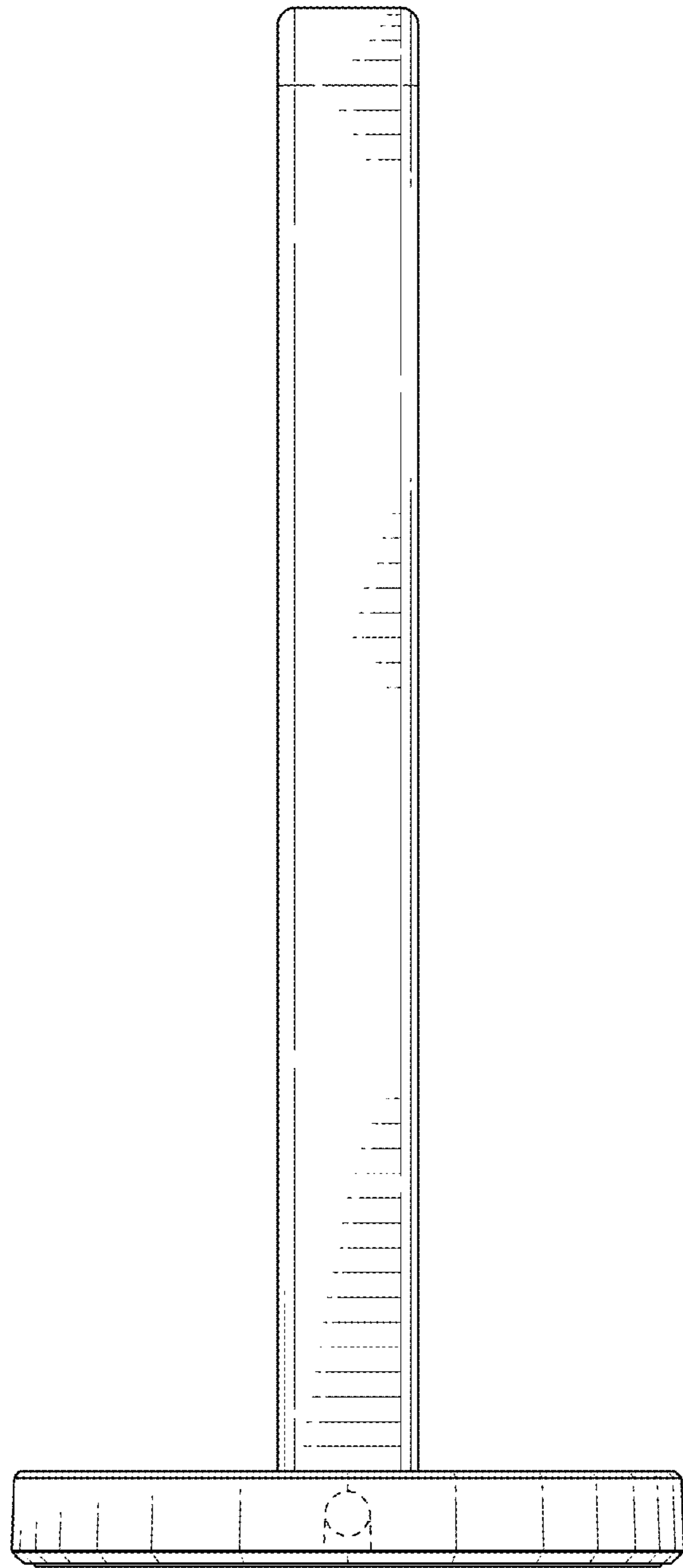


FIG. 3

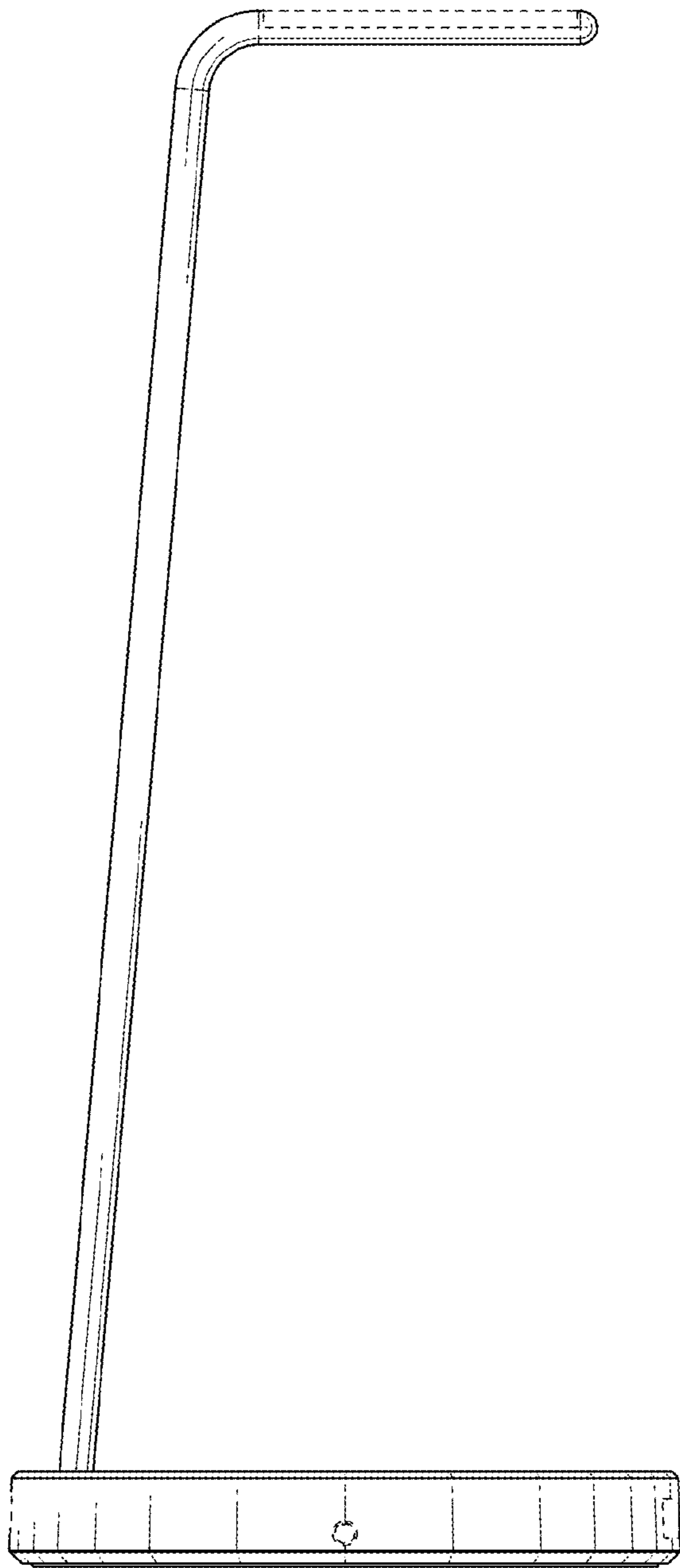


FIG. 4

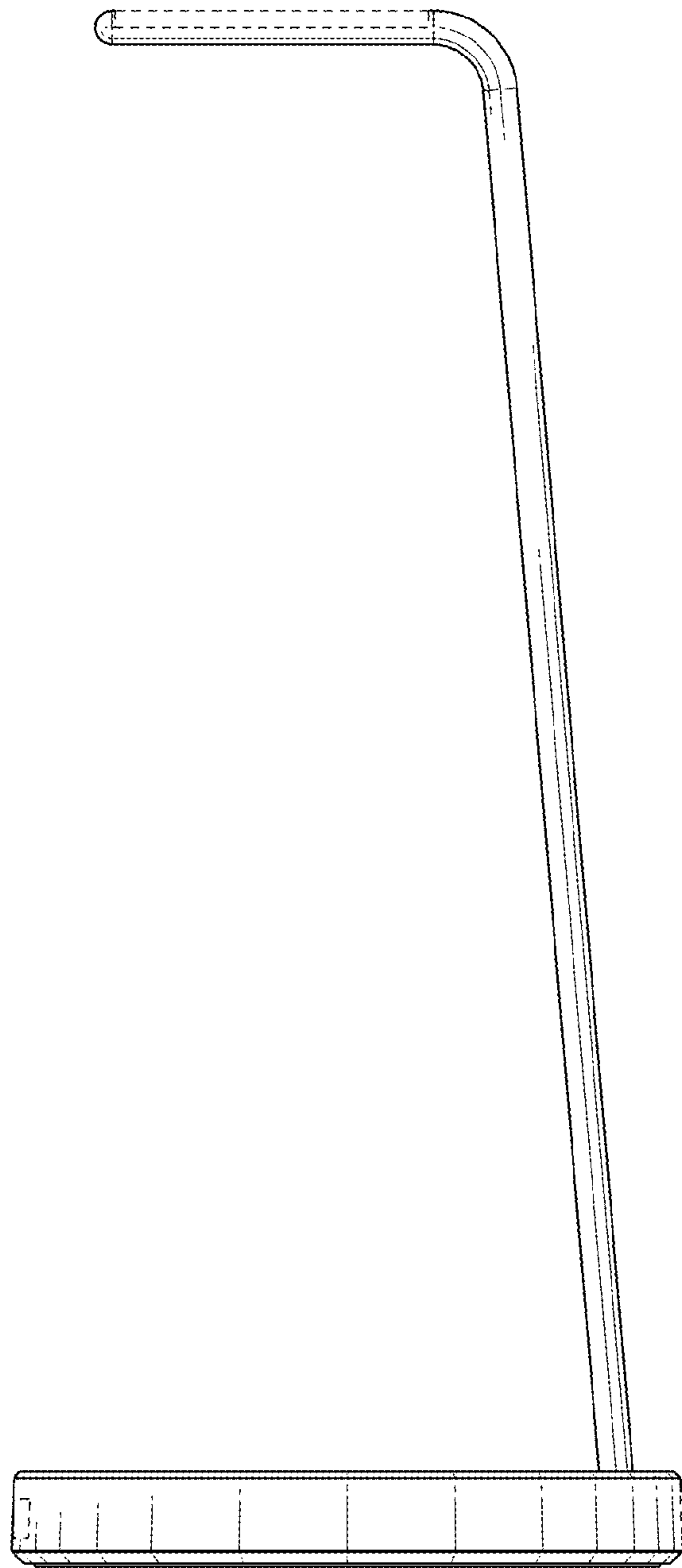


FIG. 5

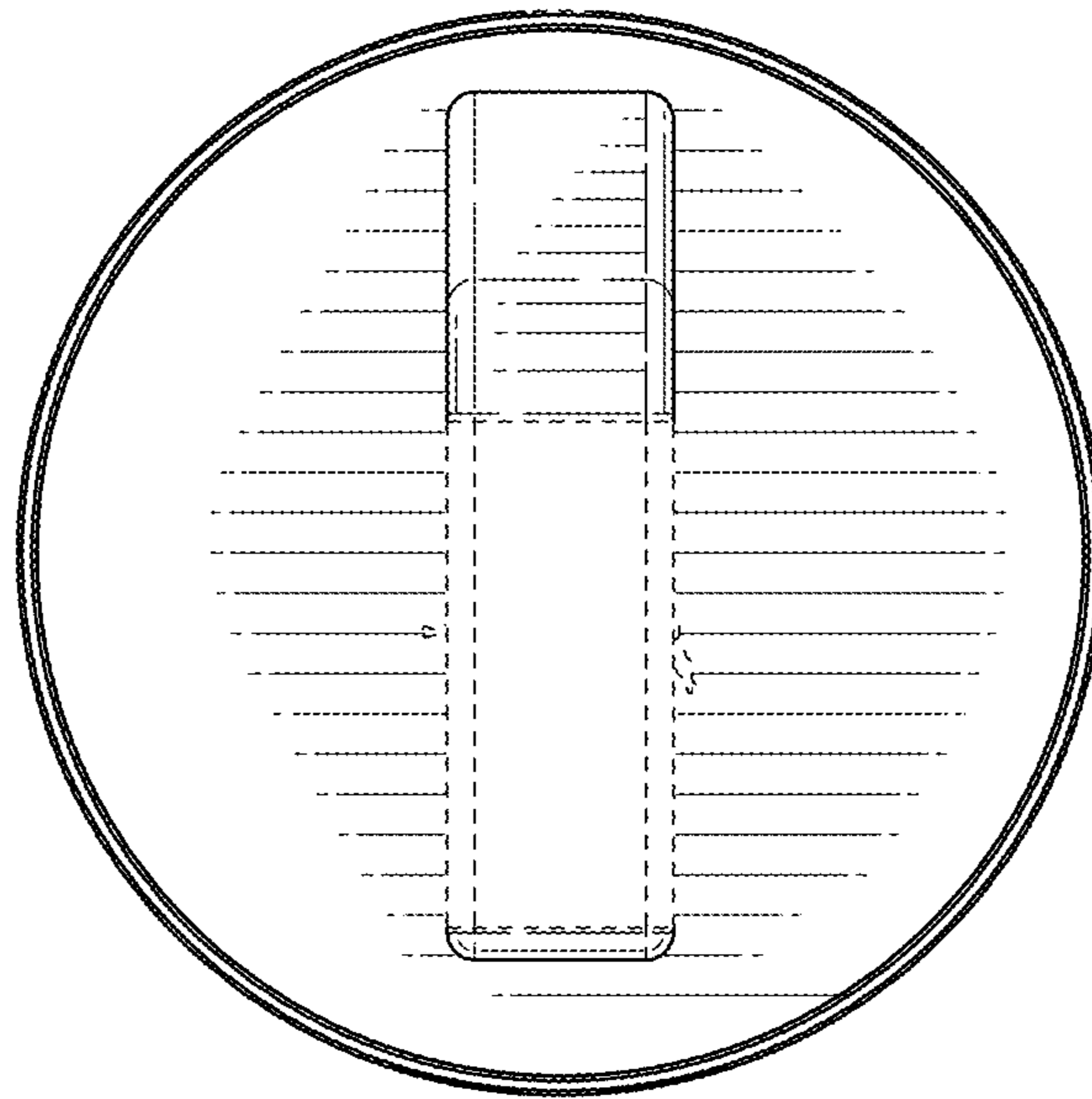


FIG. 6

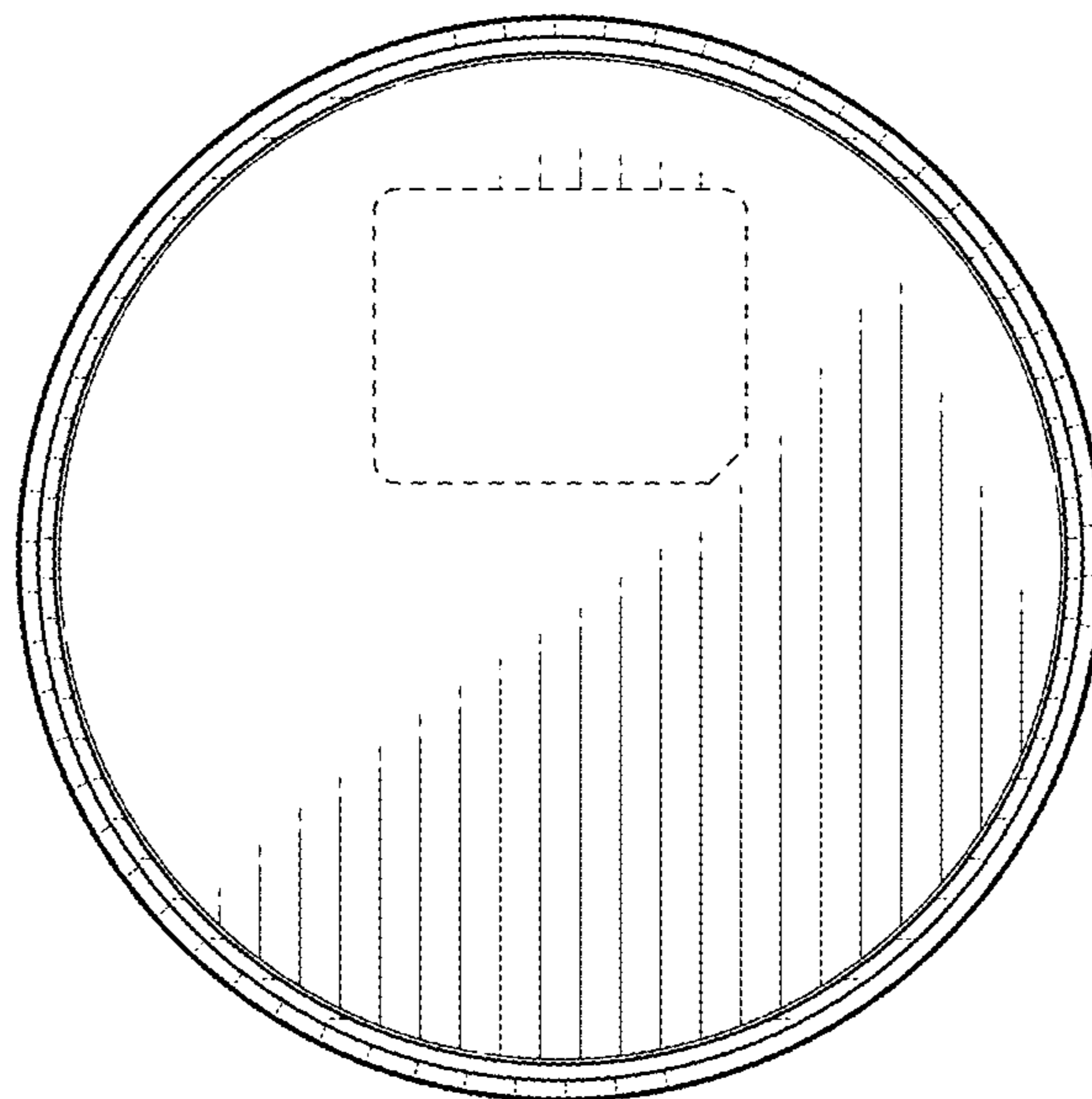


FIG. 7

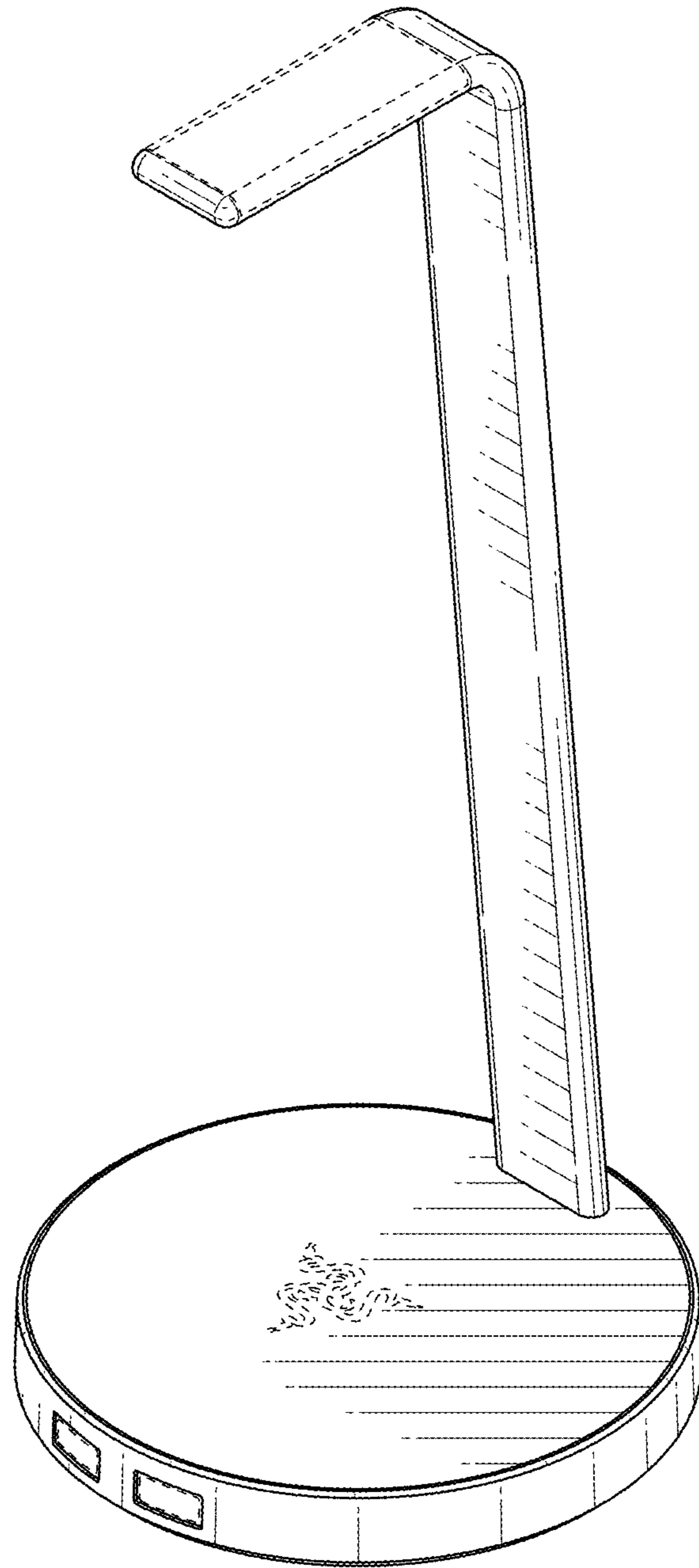


FIG. 8

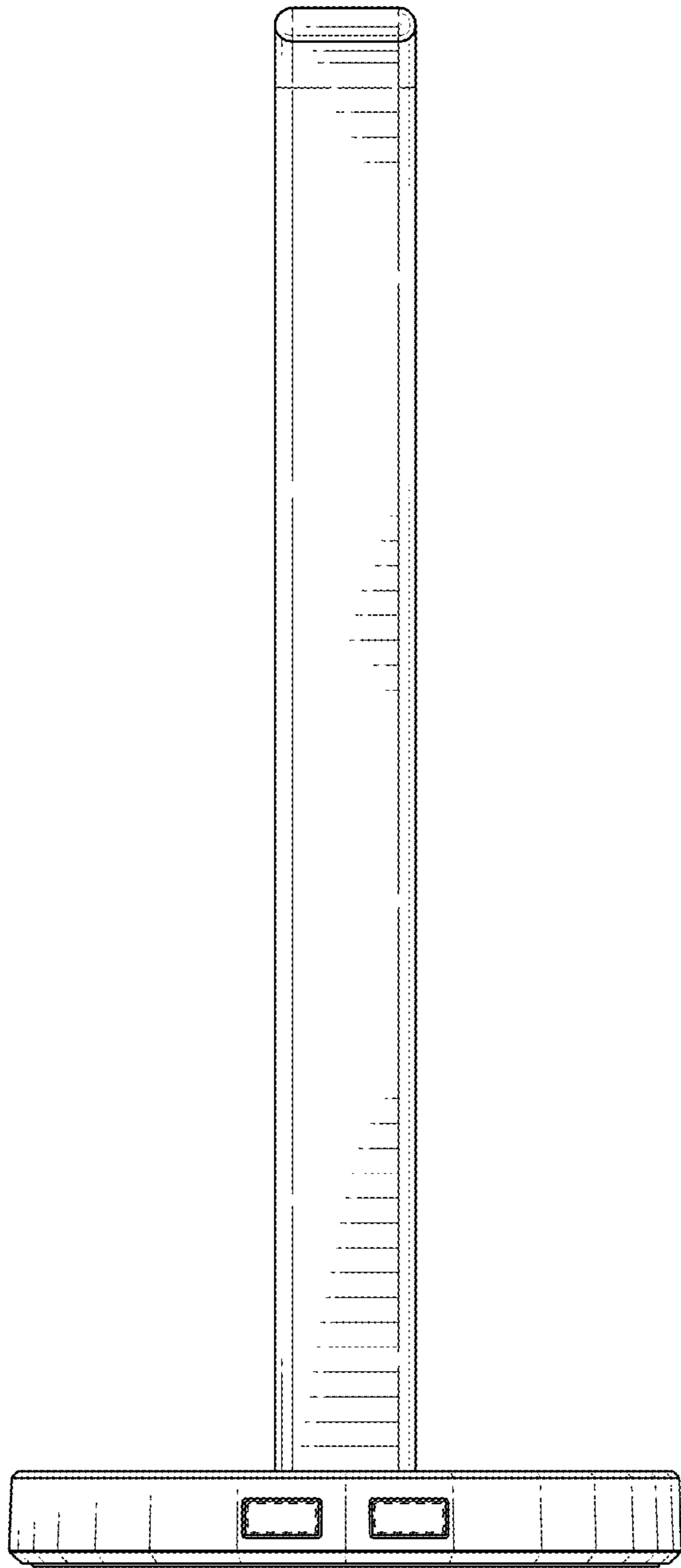


FIG. 9

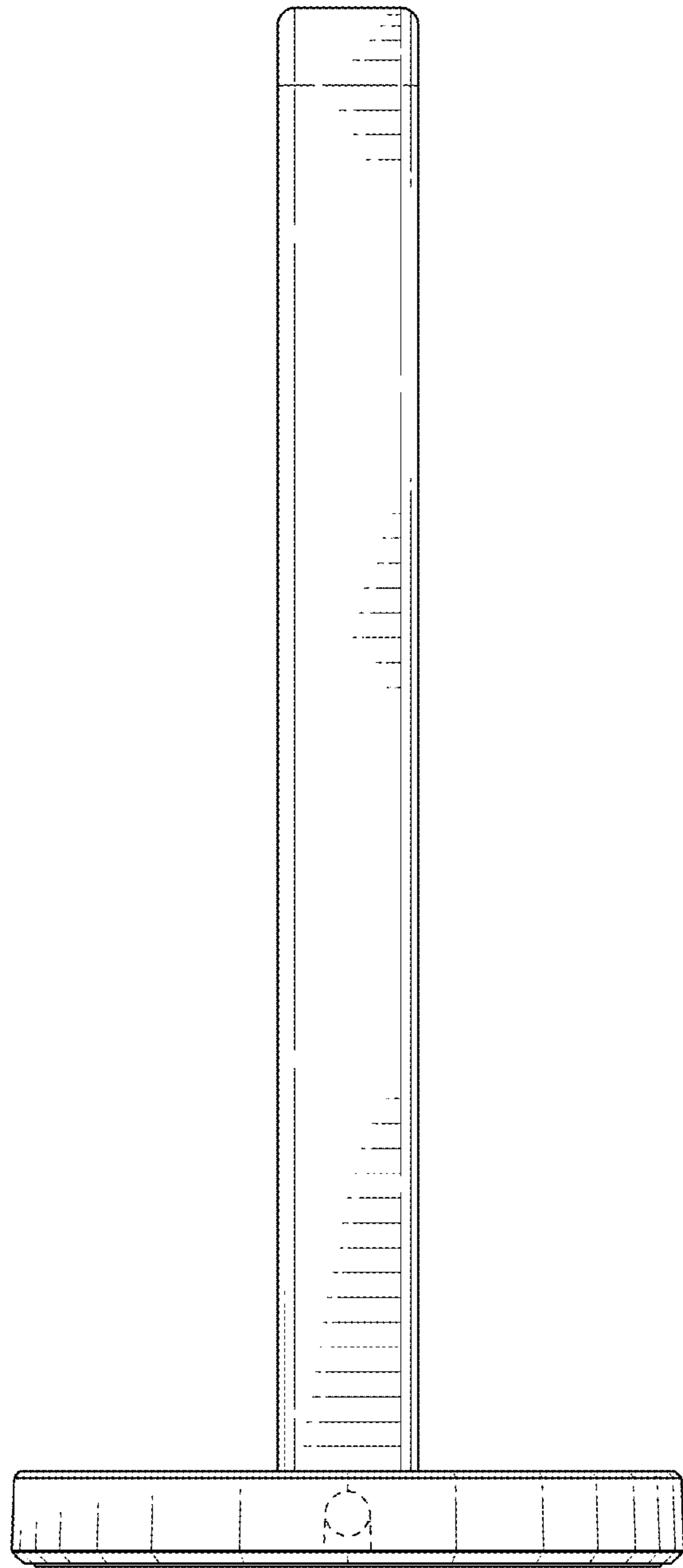


FIG. 10

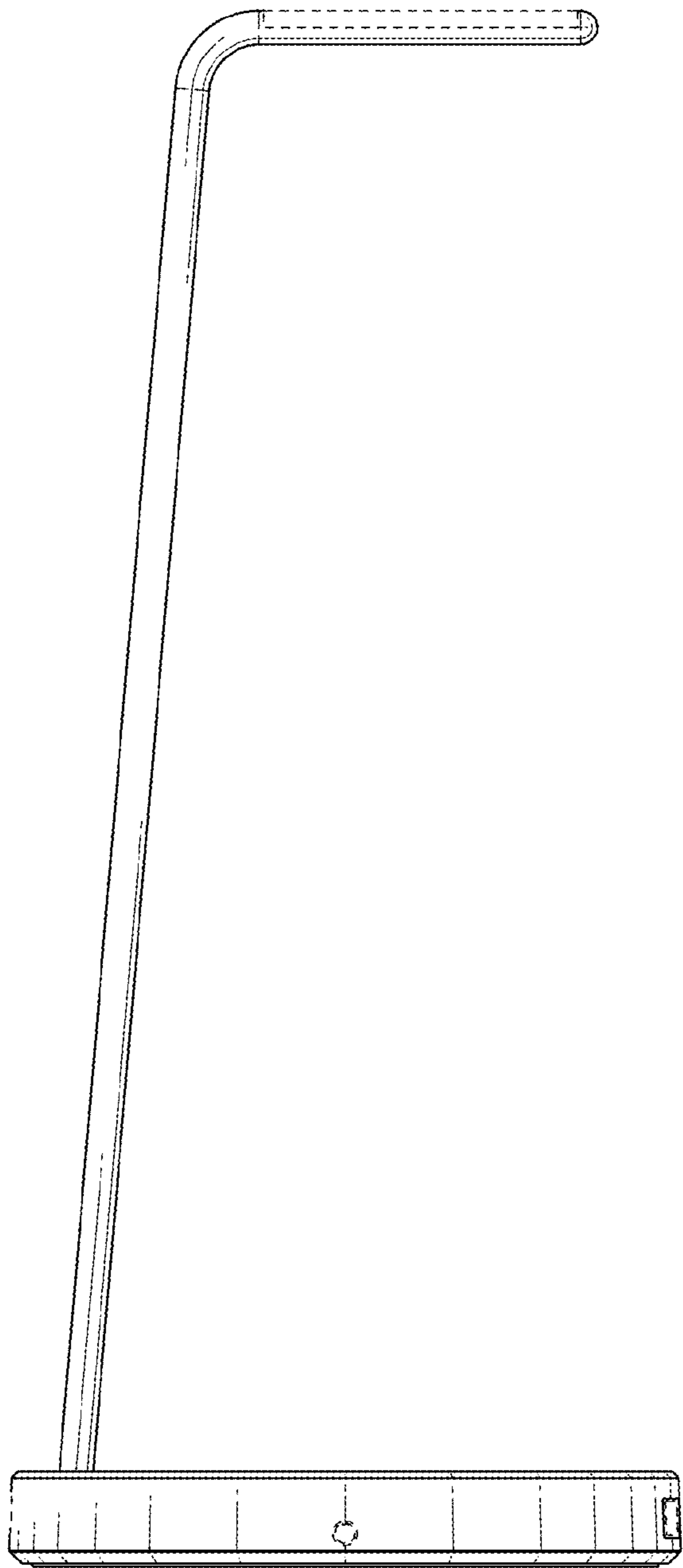


FIG. 11

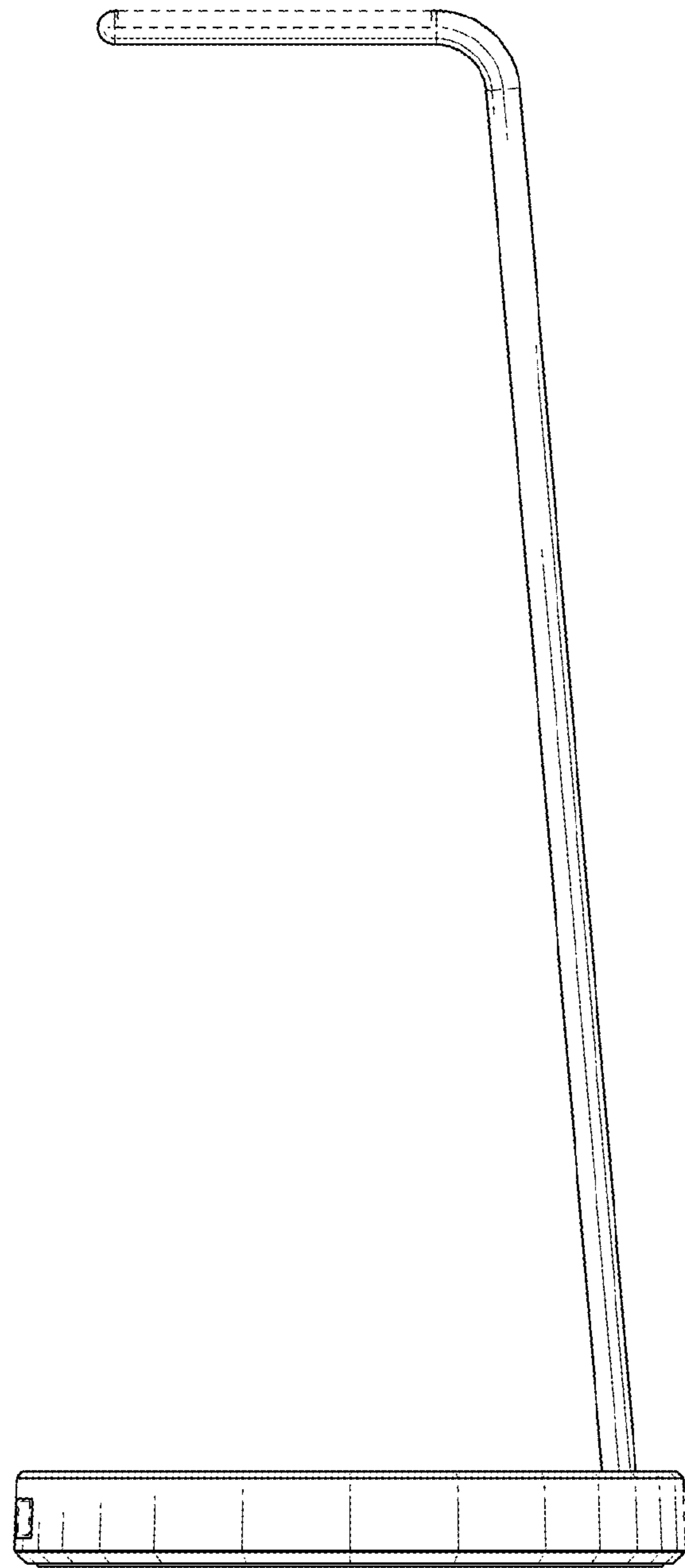


FIG. 12

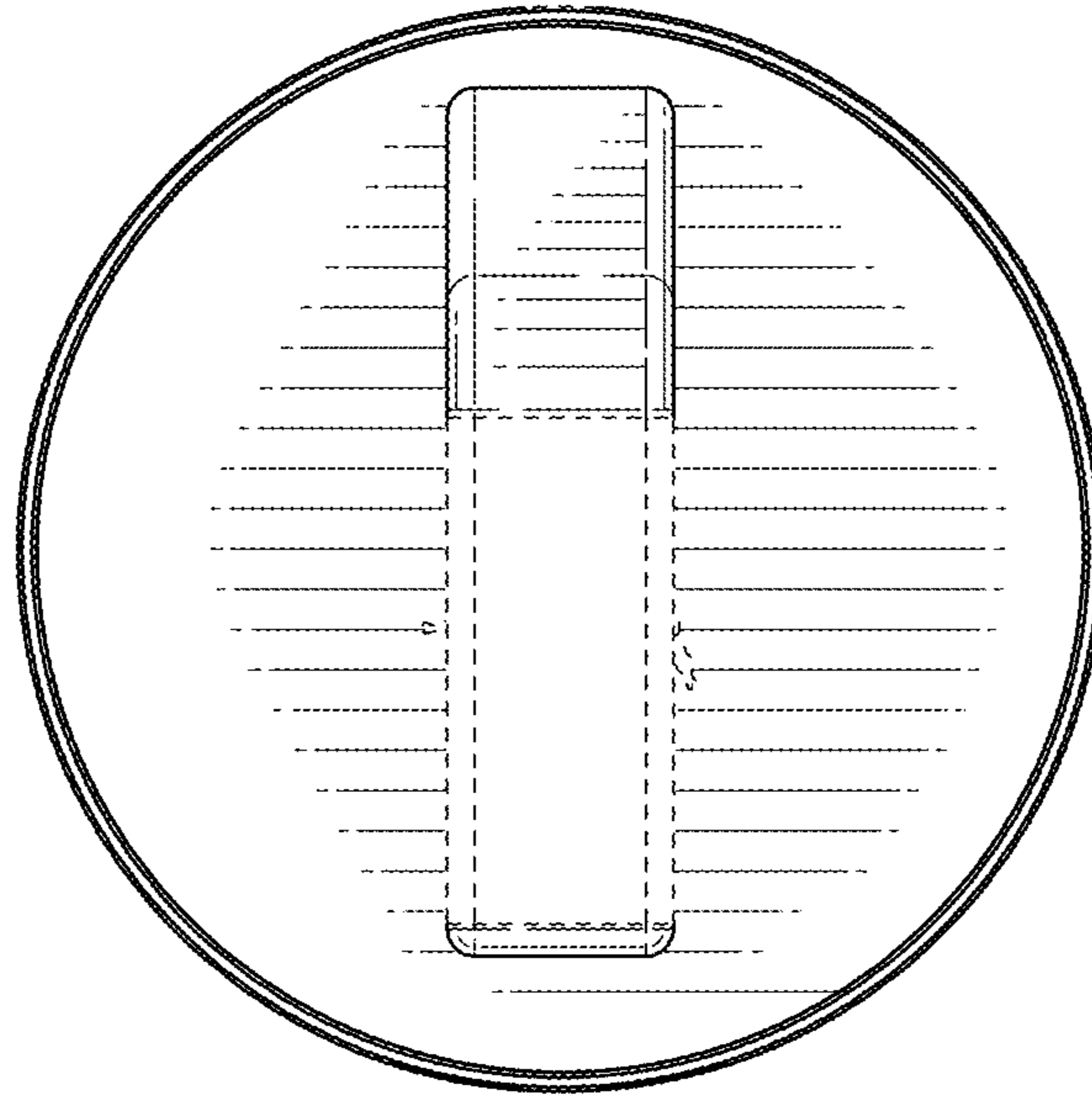


FIG. 13

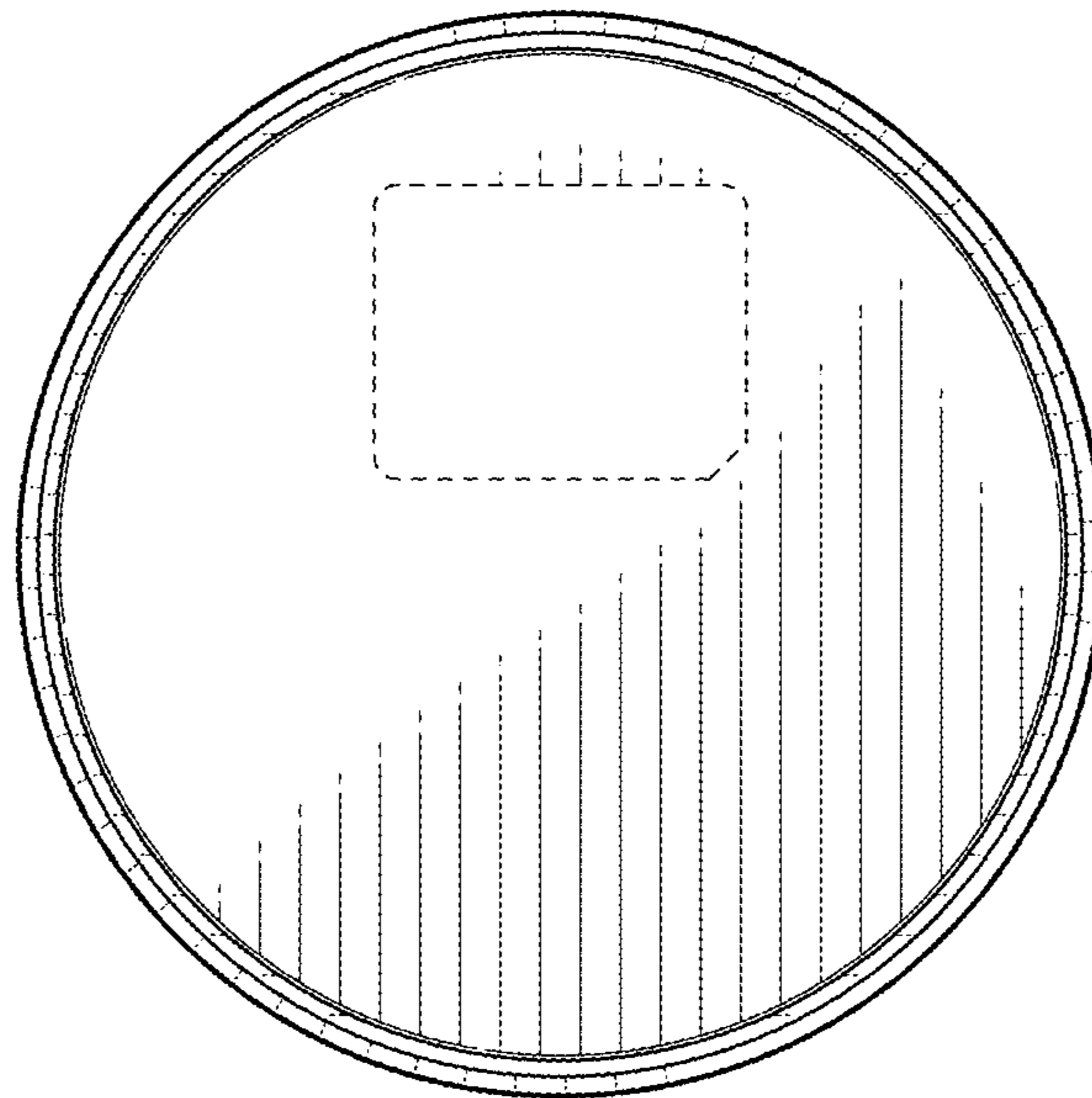


FIG. 14

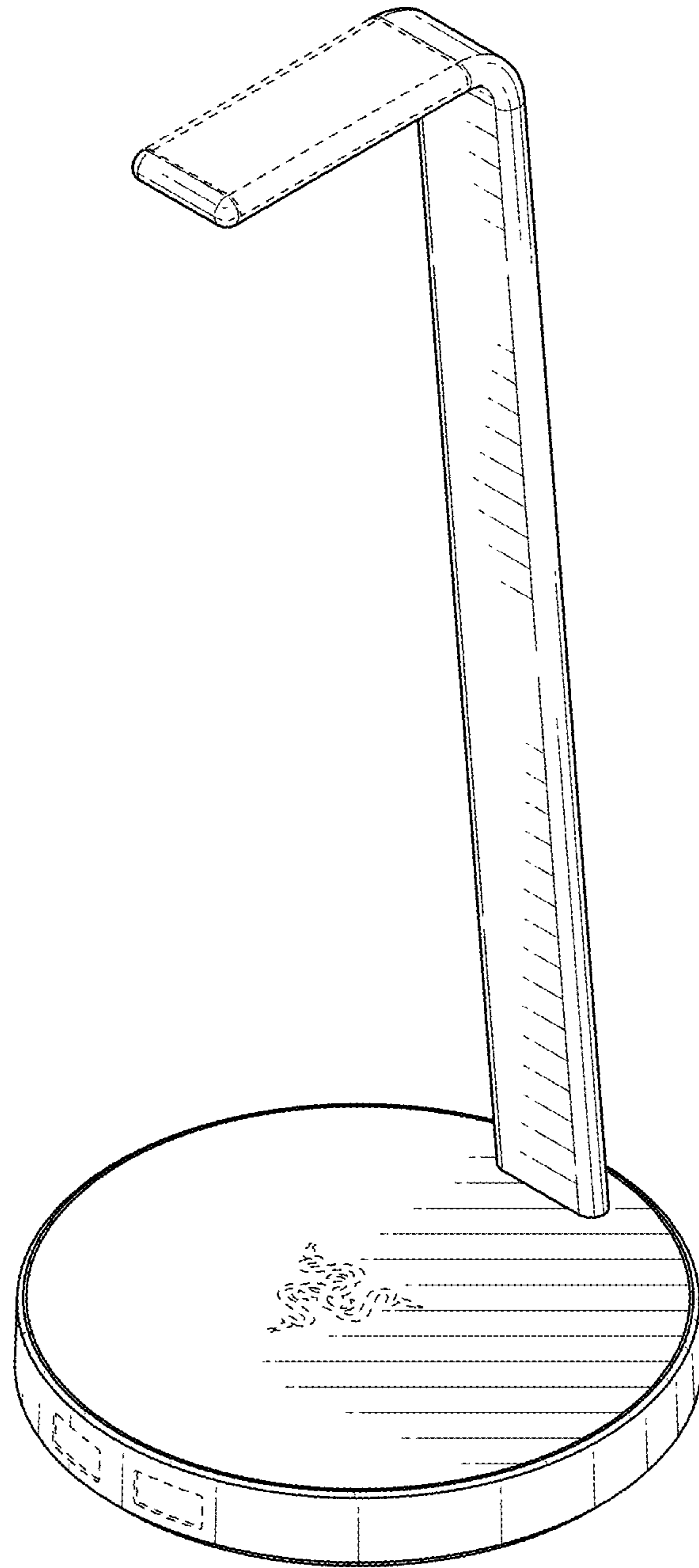


FIG. 15

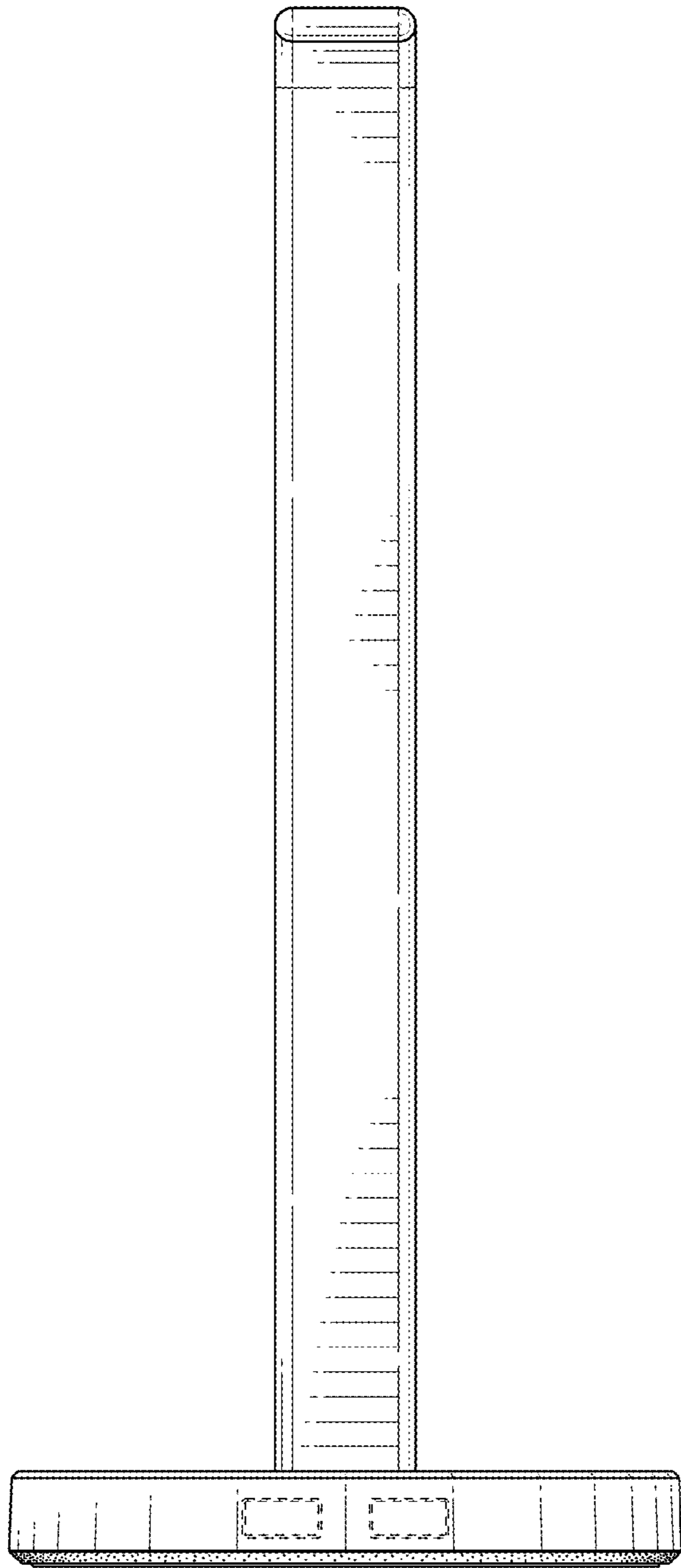


FIG. 16

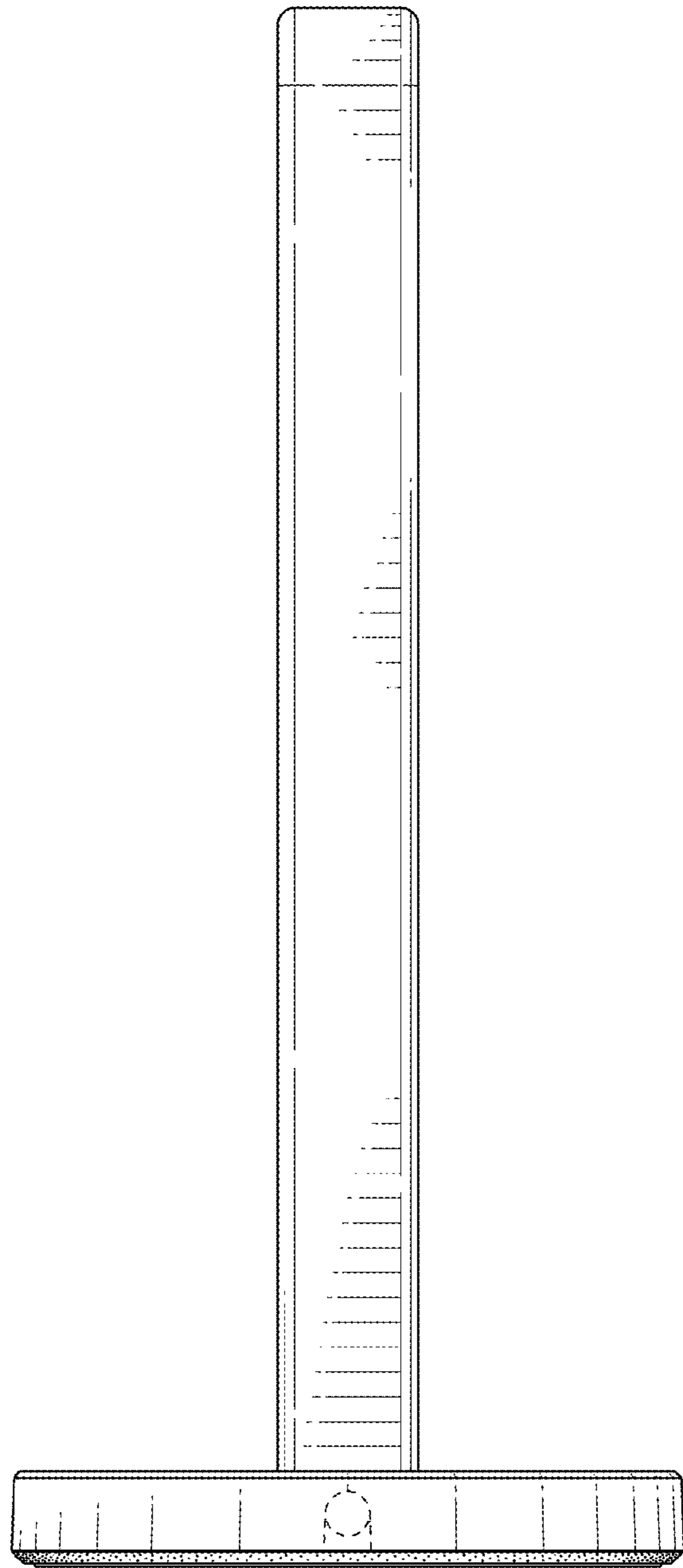


FIG. 17

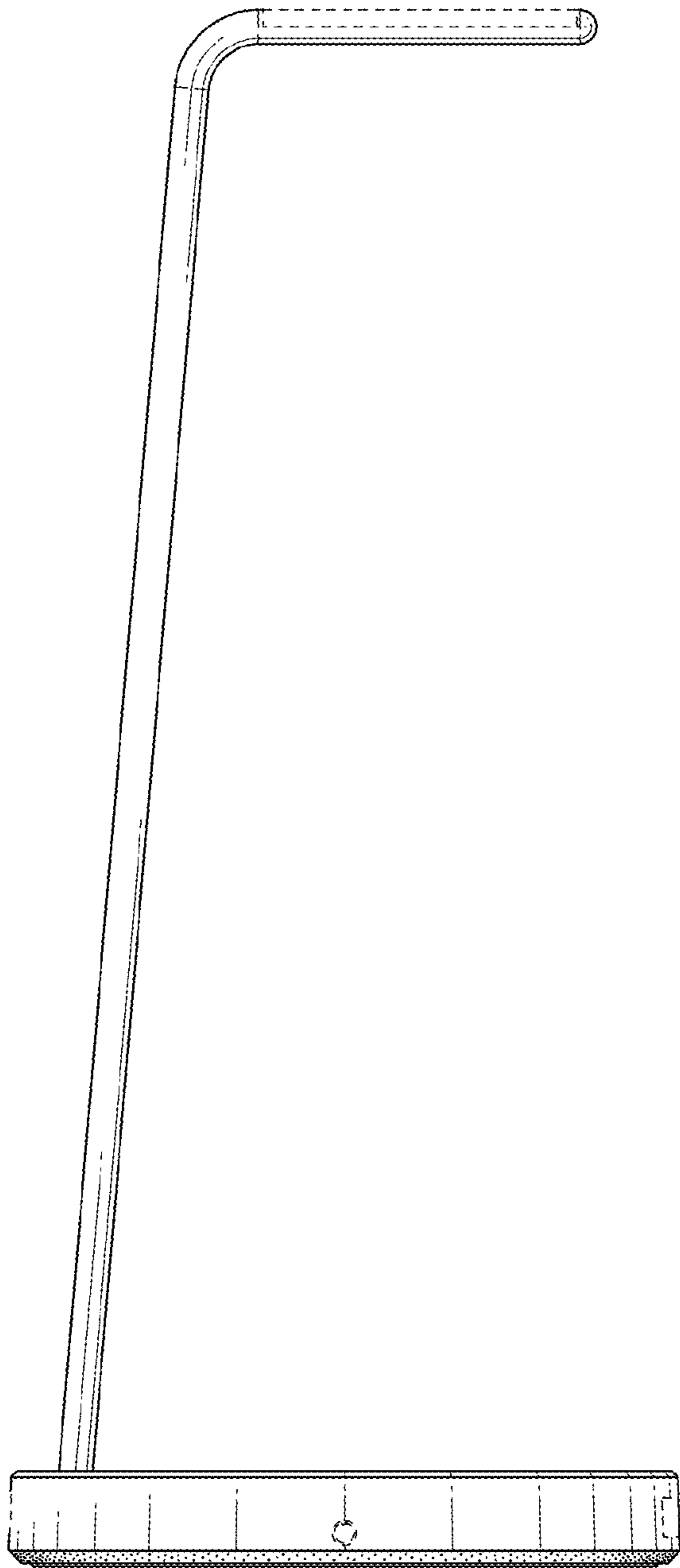


FIG. 18

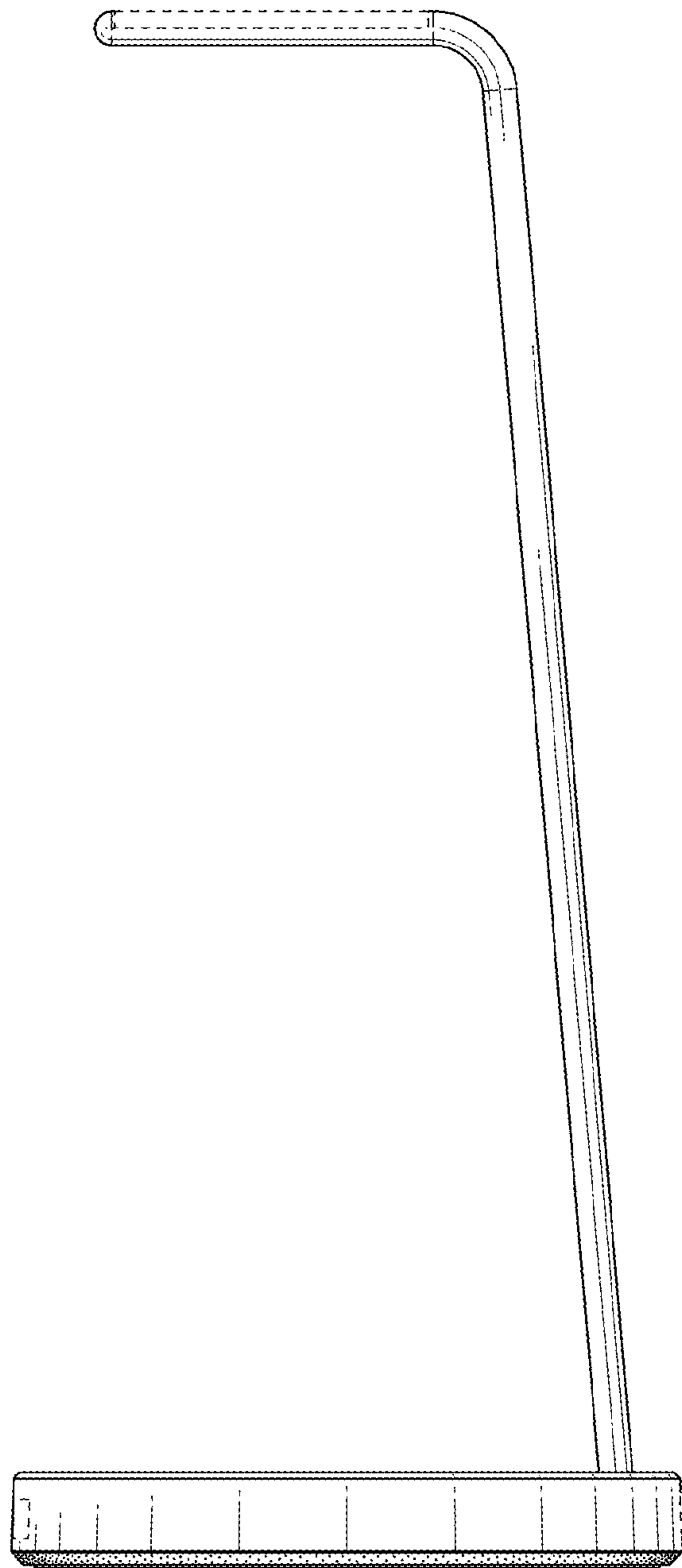


FIG. 19

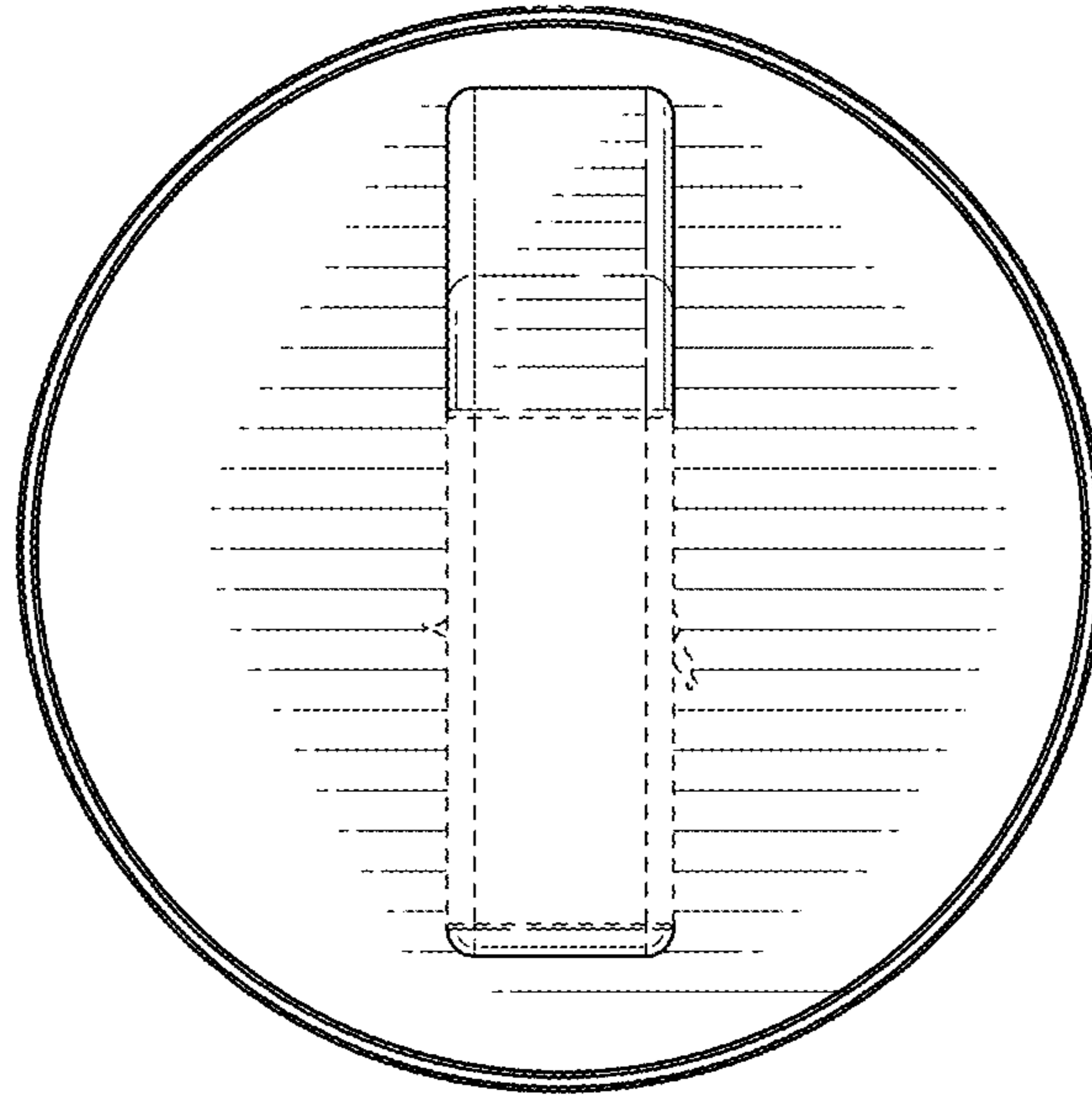


FIG. 20

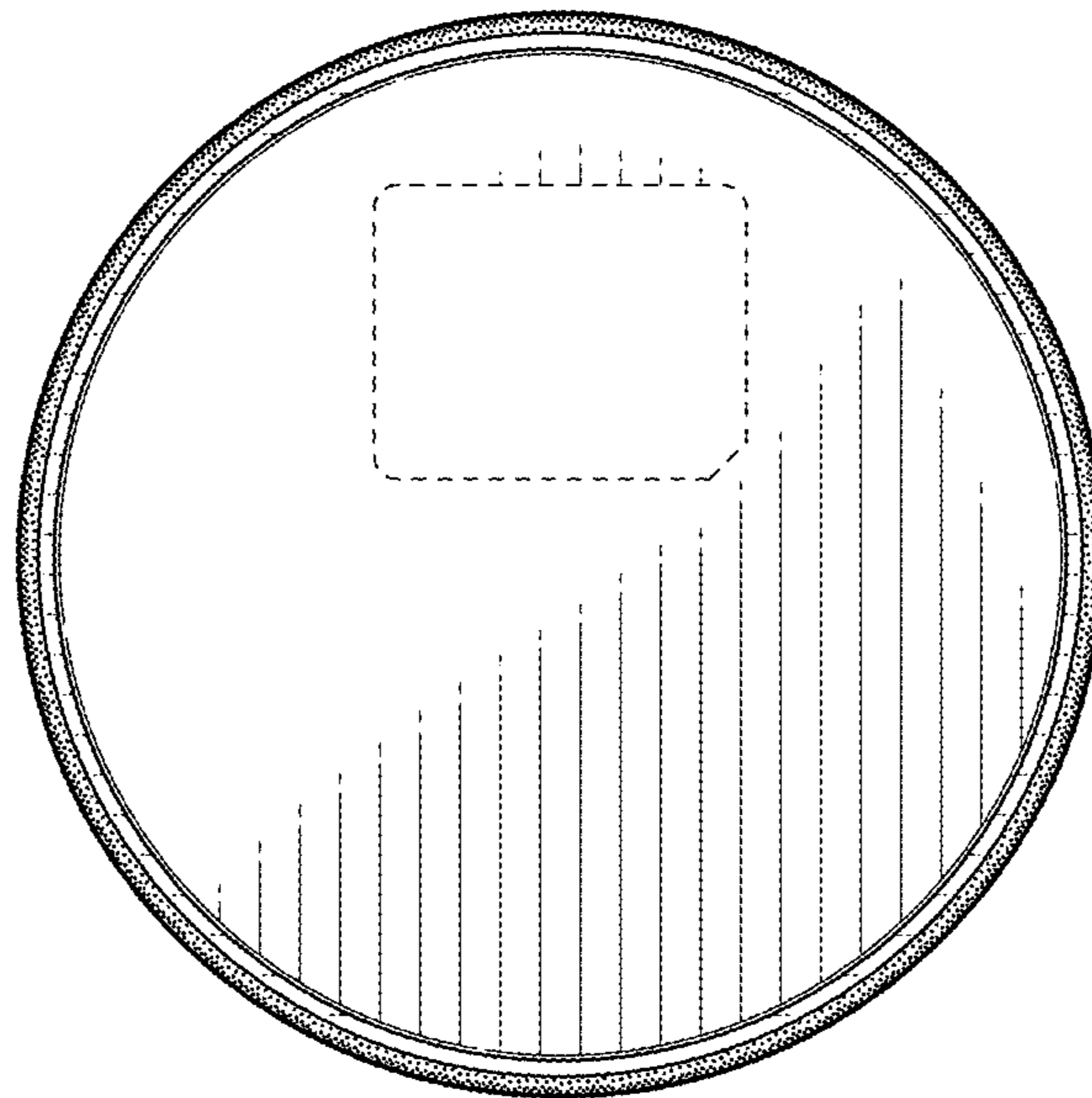


FIG. 21

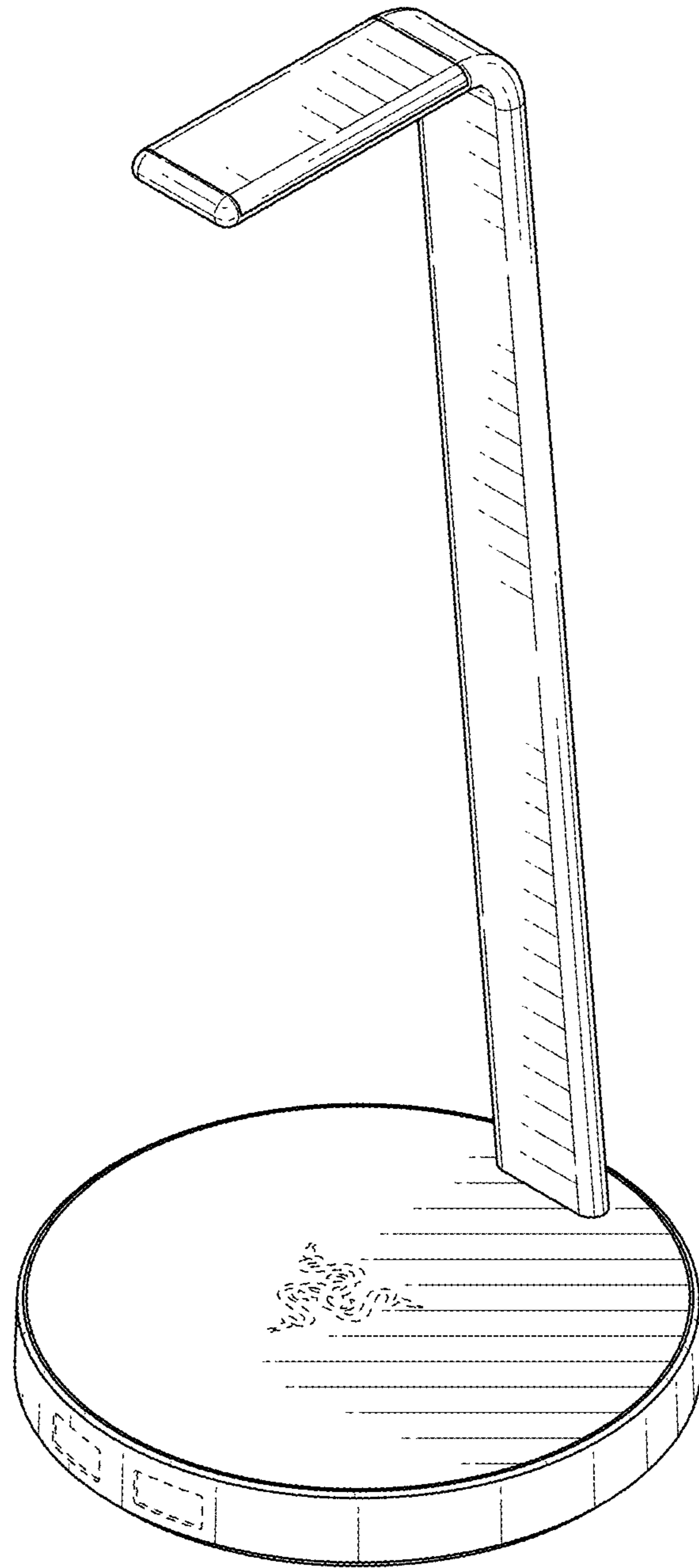


FIG. 22

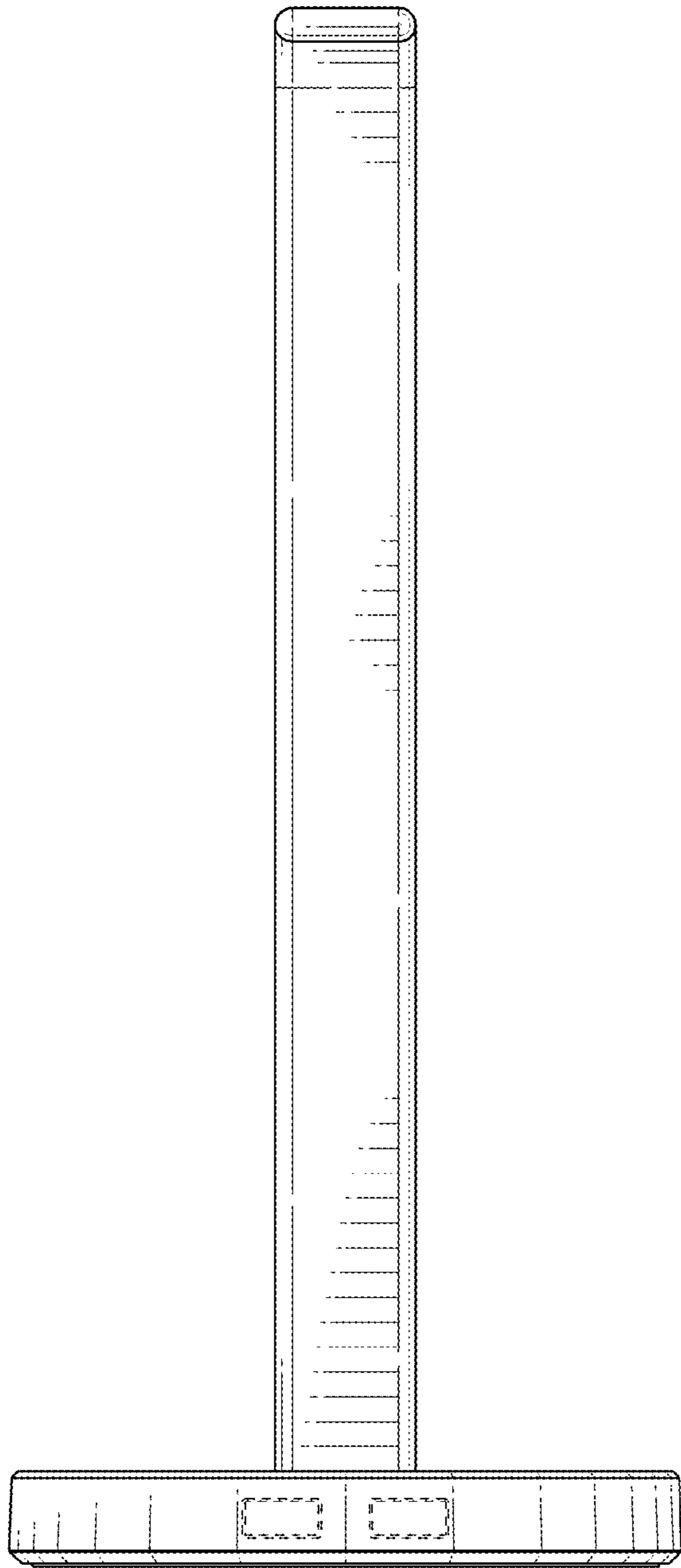


FIG. 23

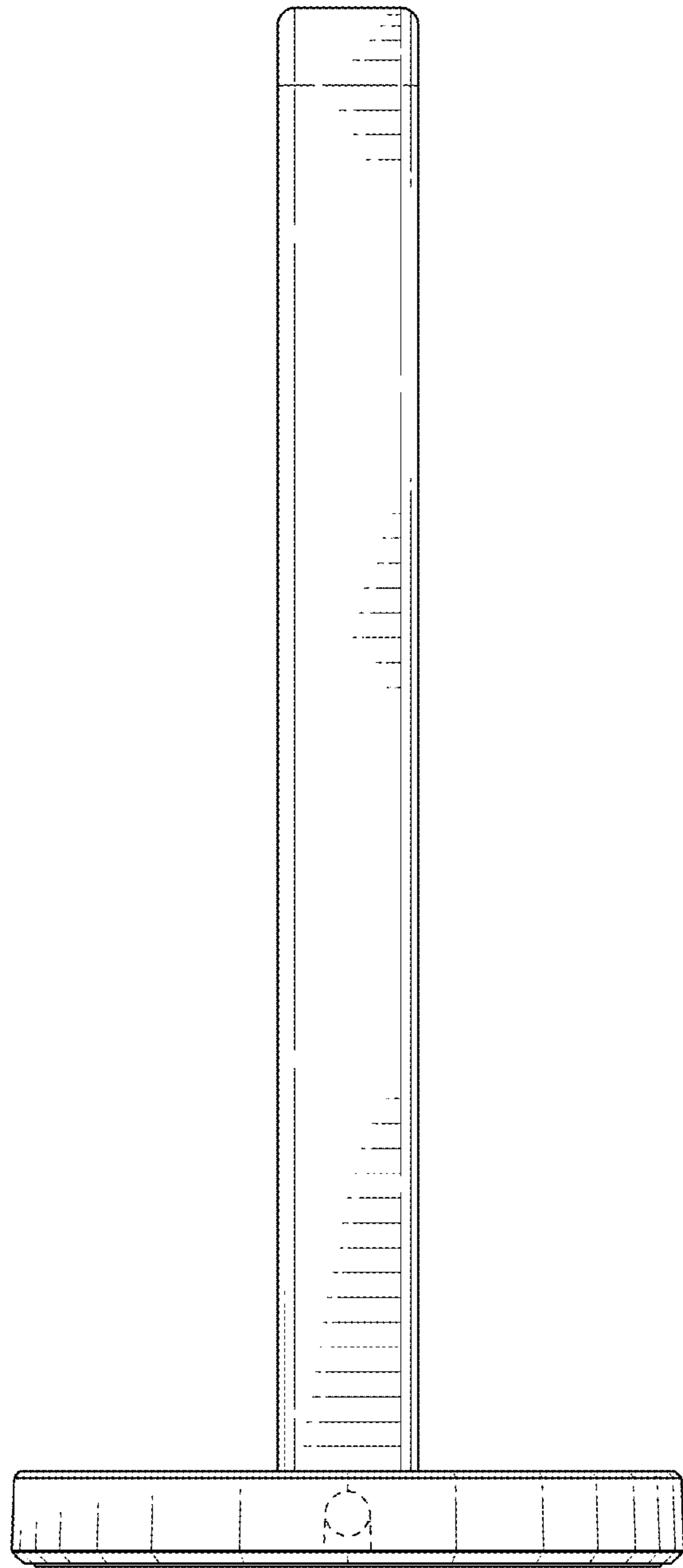


FIG. 24

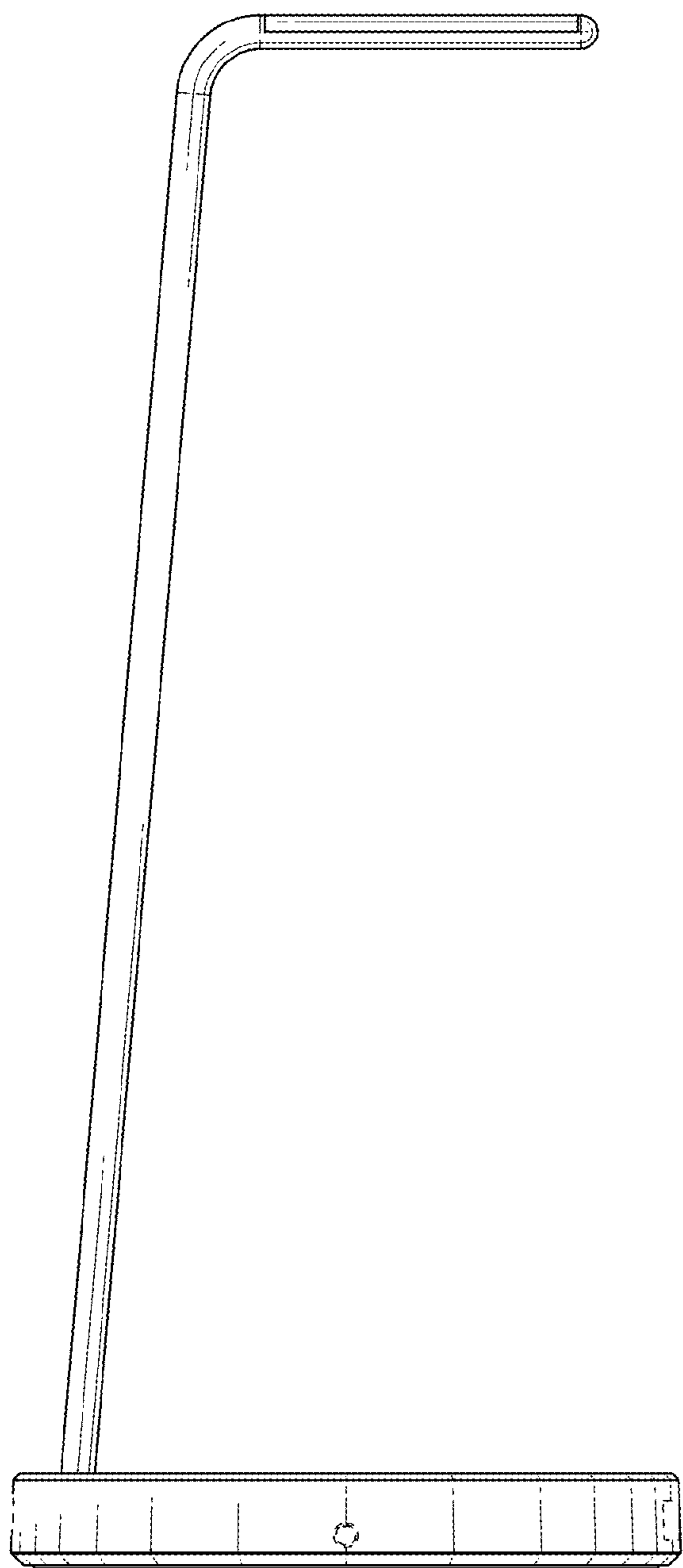


FIG. 25

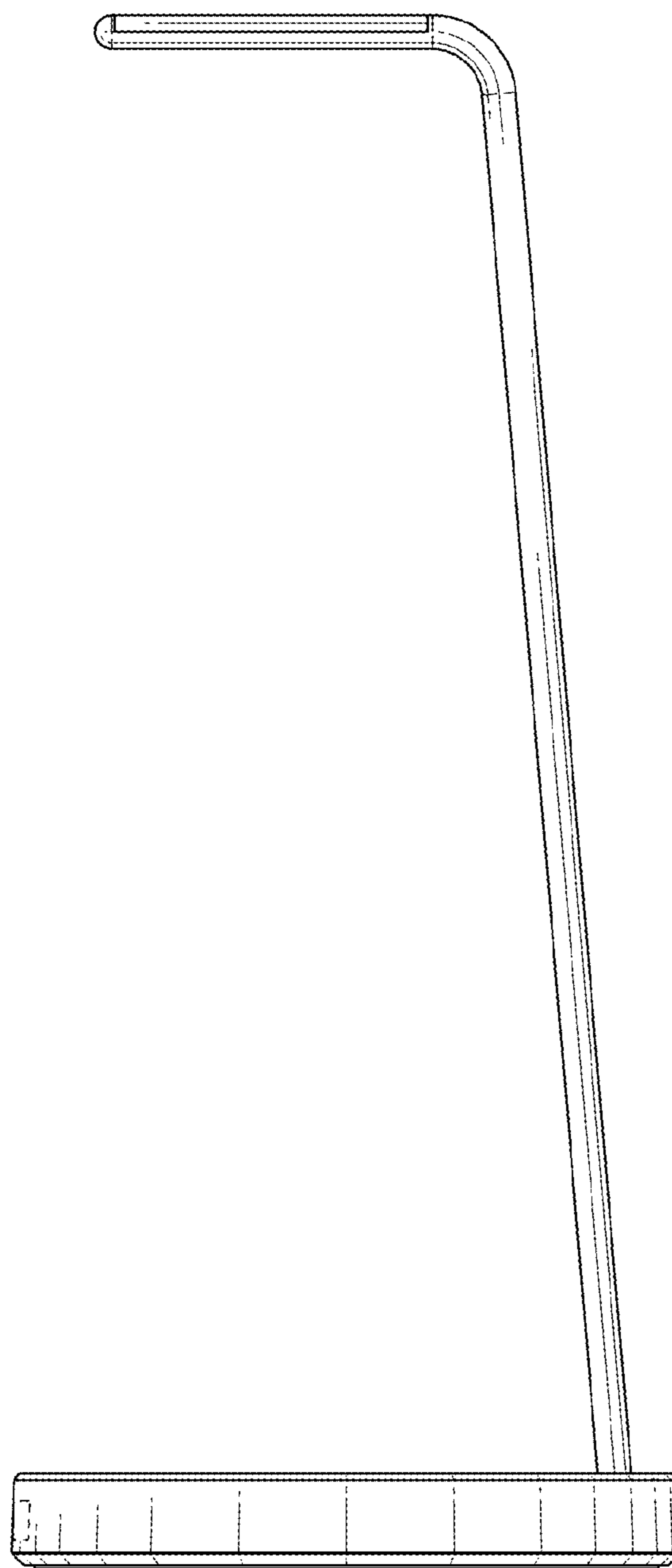


FIG. 26

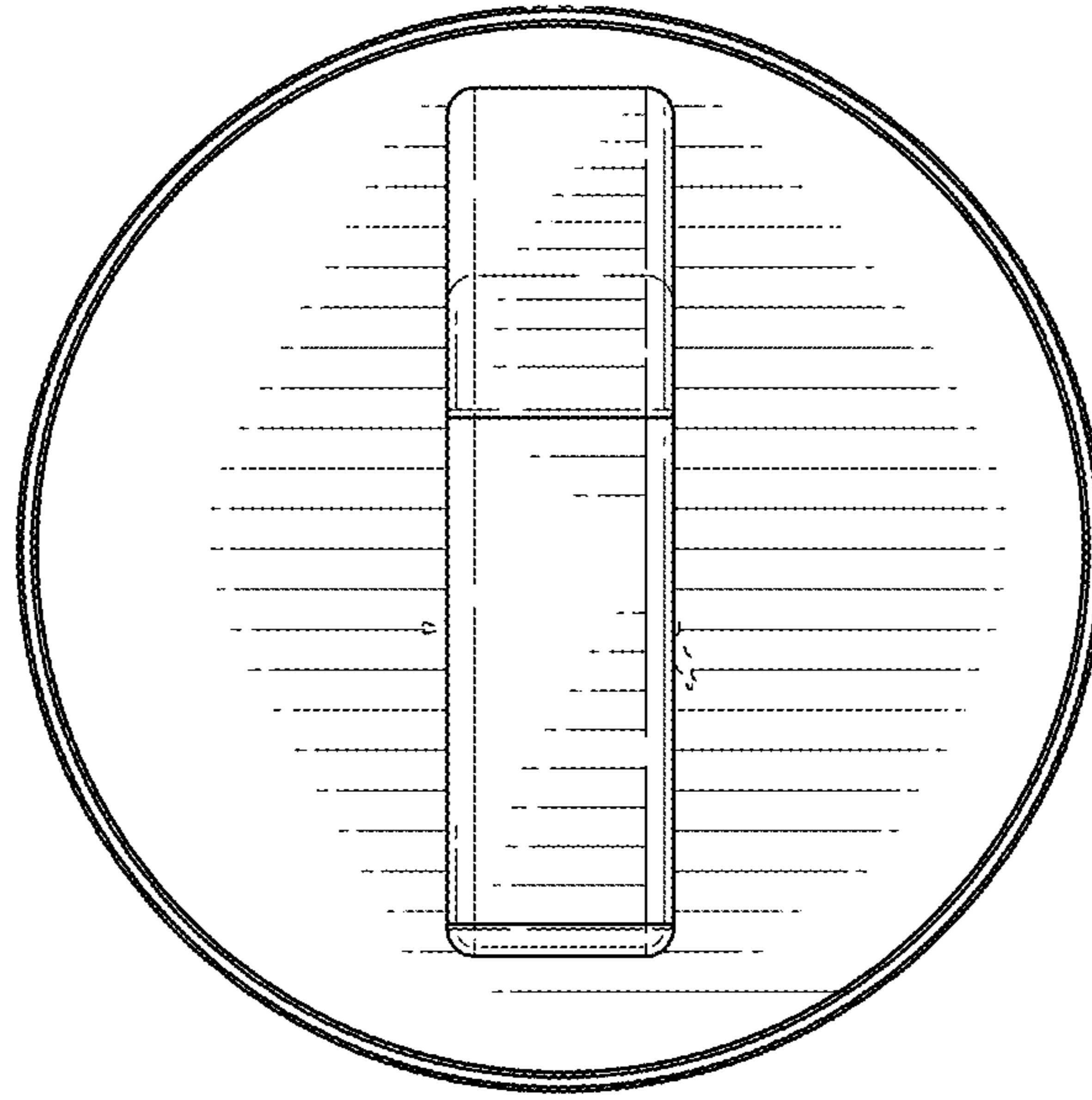


FIG. 27

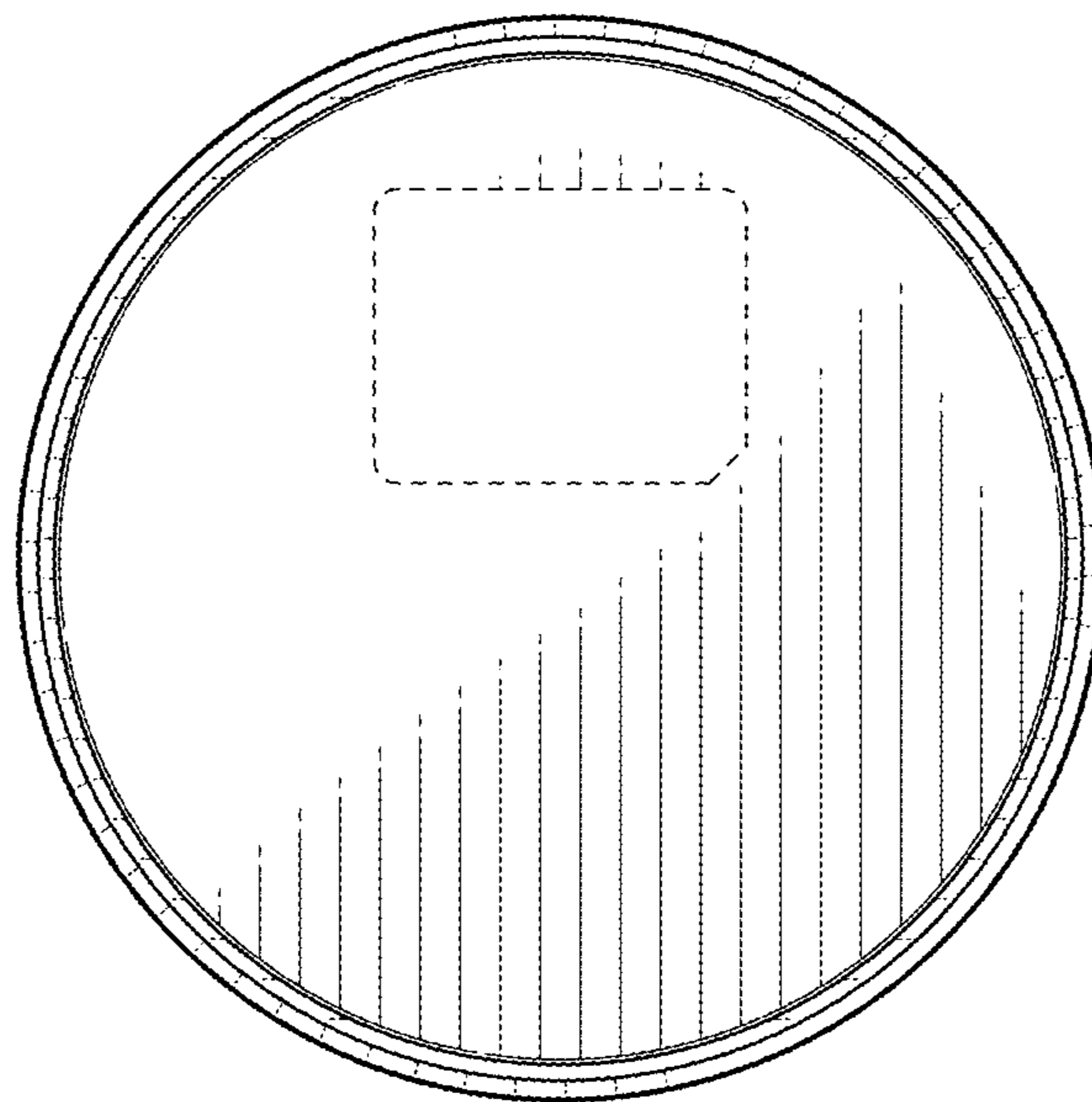


FIG. 28

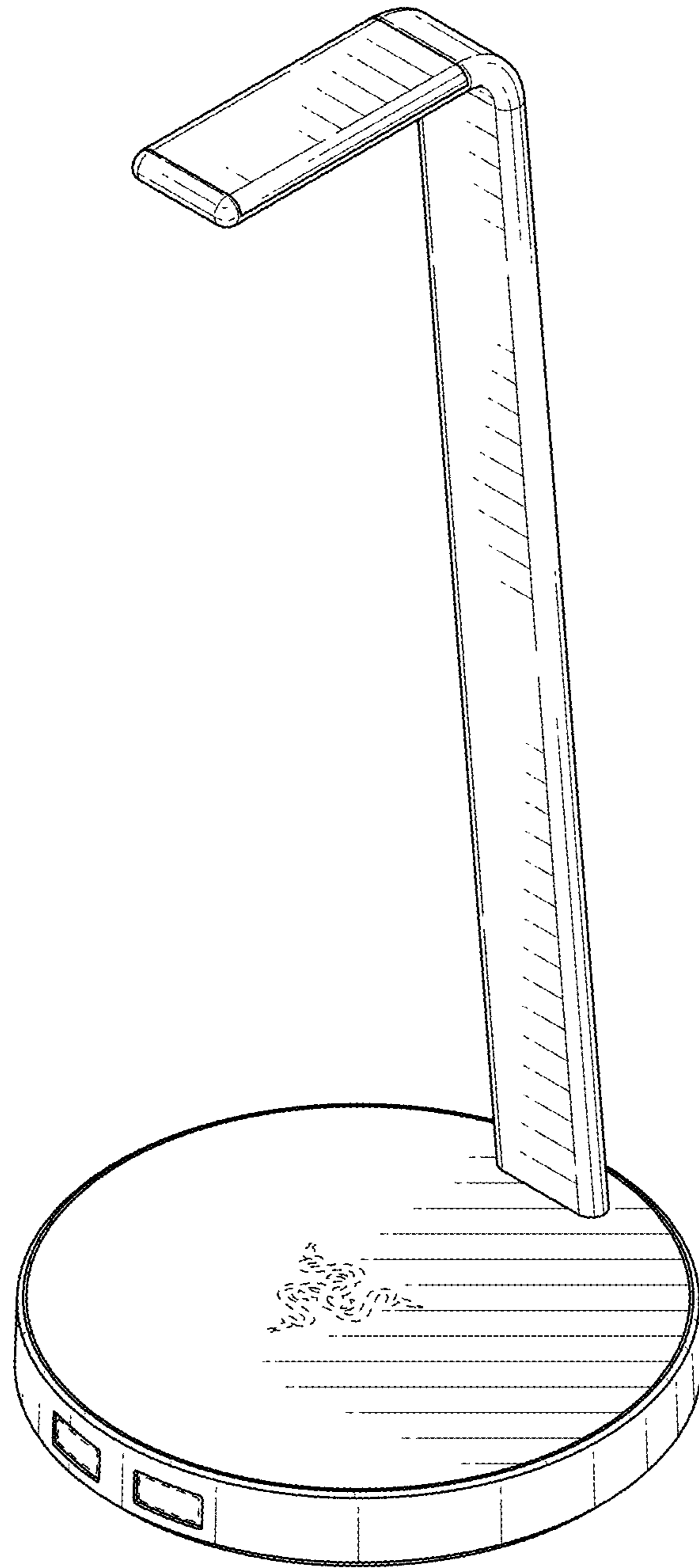


FIG. 29

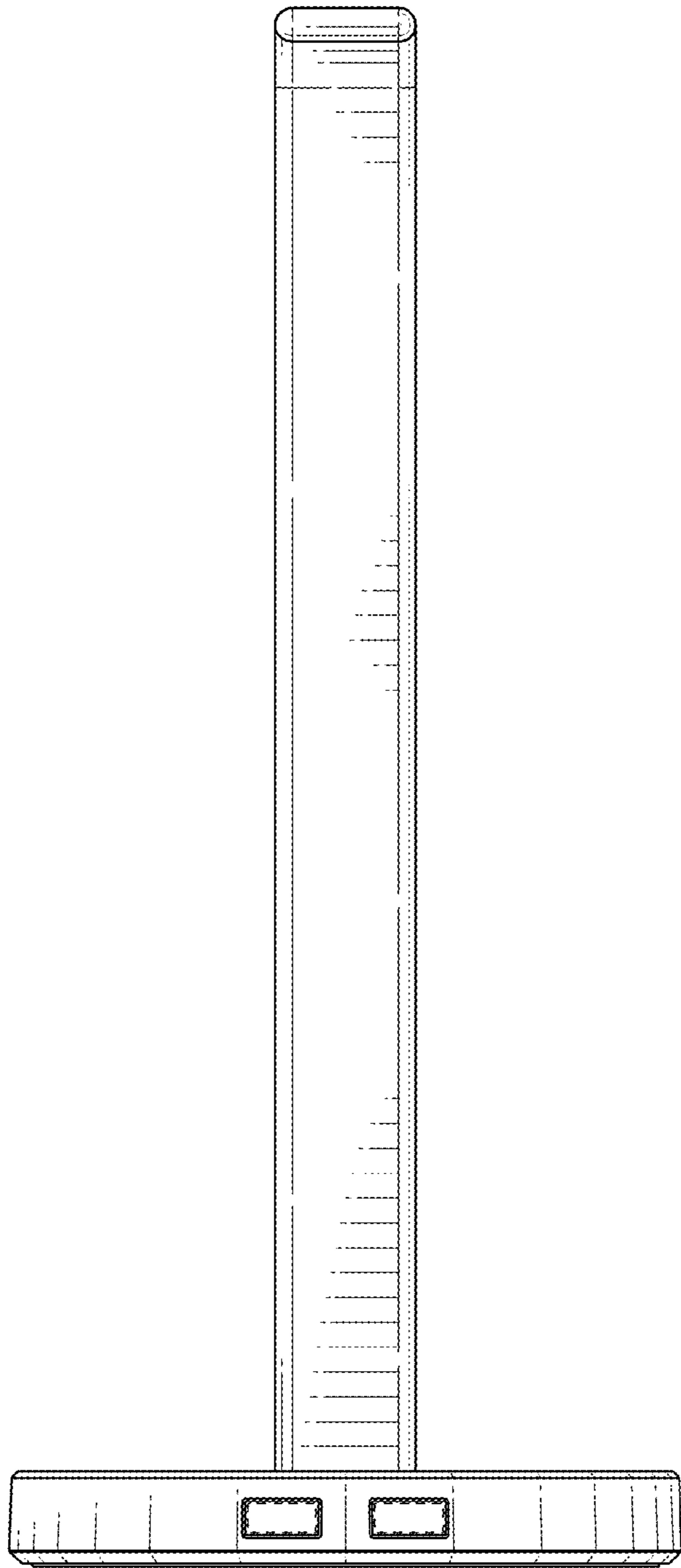


FIG. 30

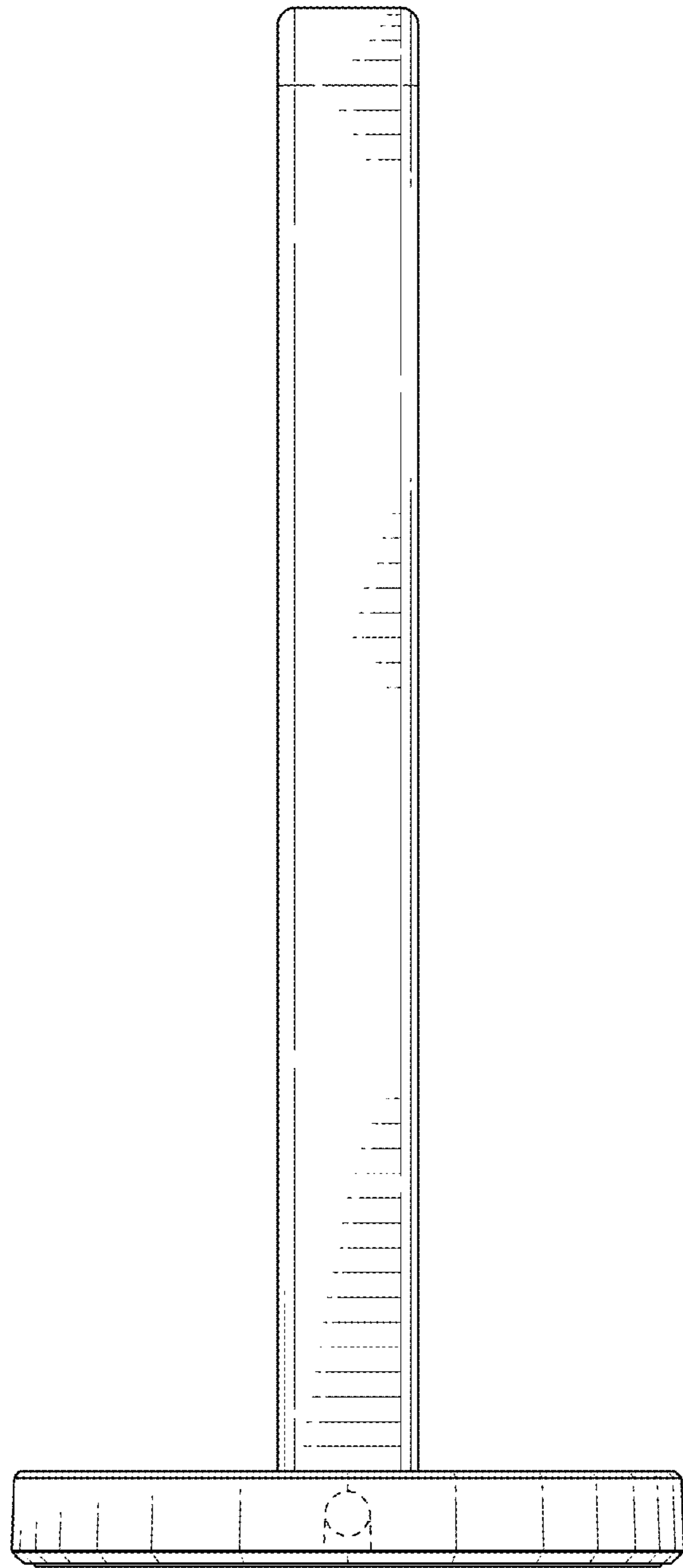


FIG. 31

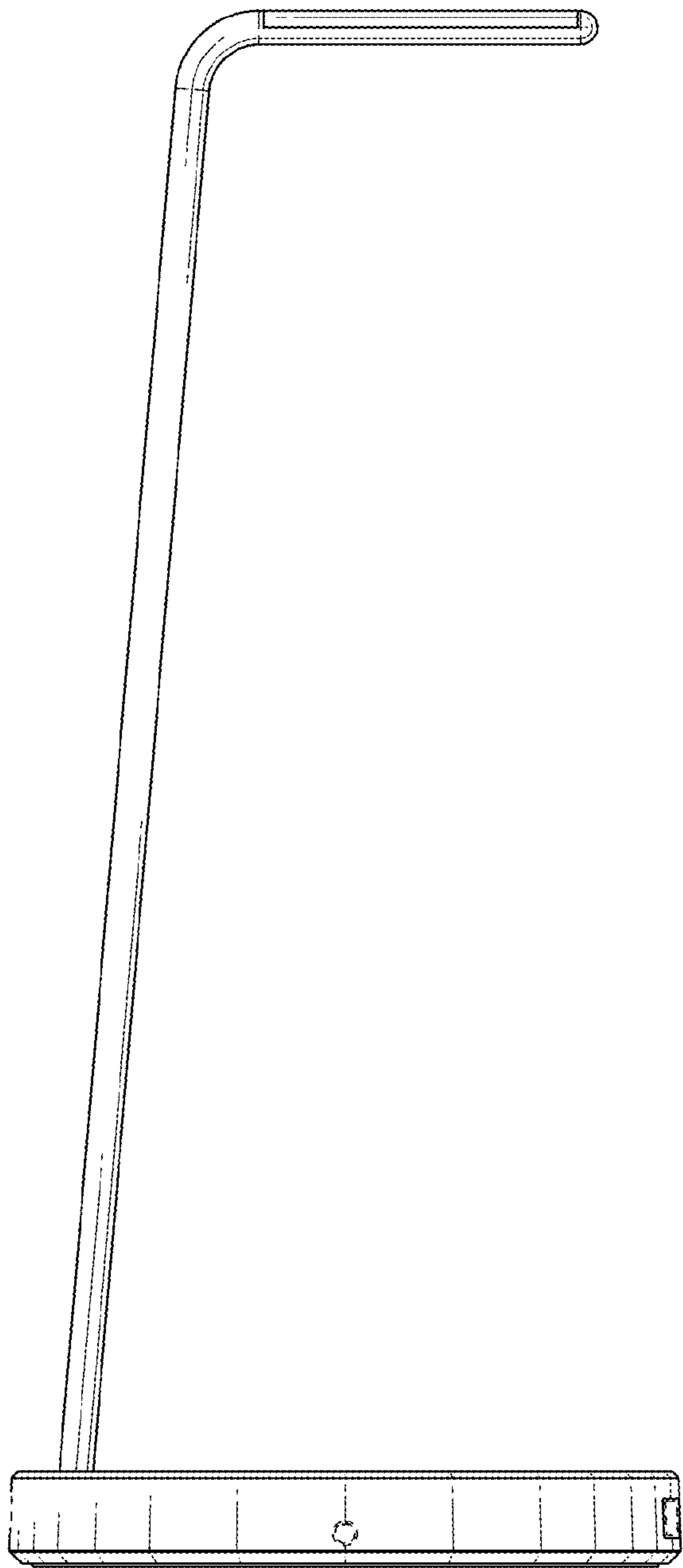


FIG. 32

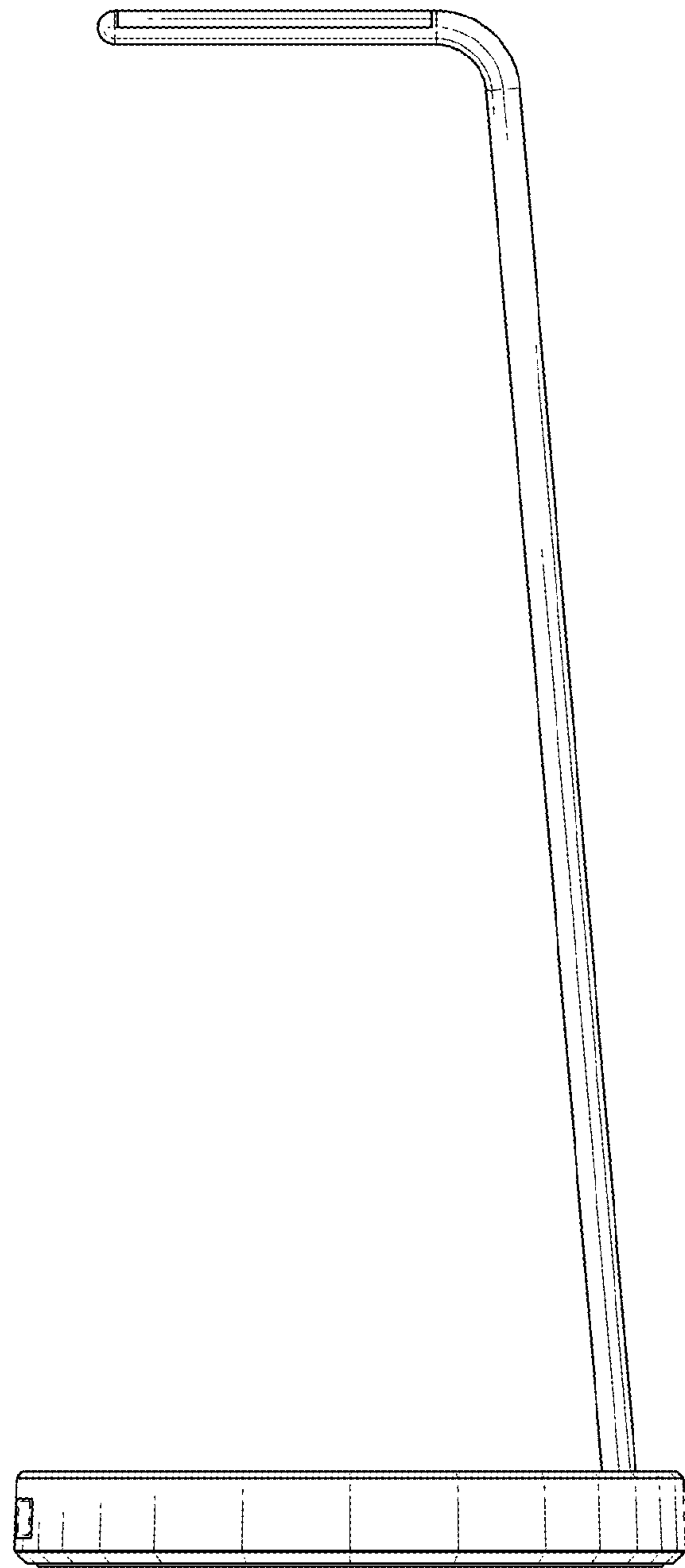


FIG. 33

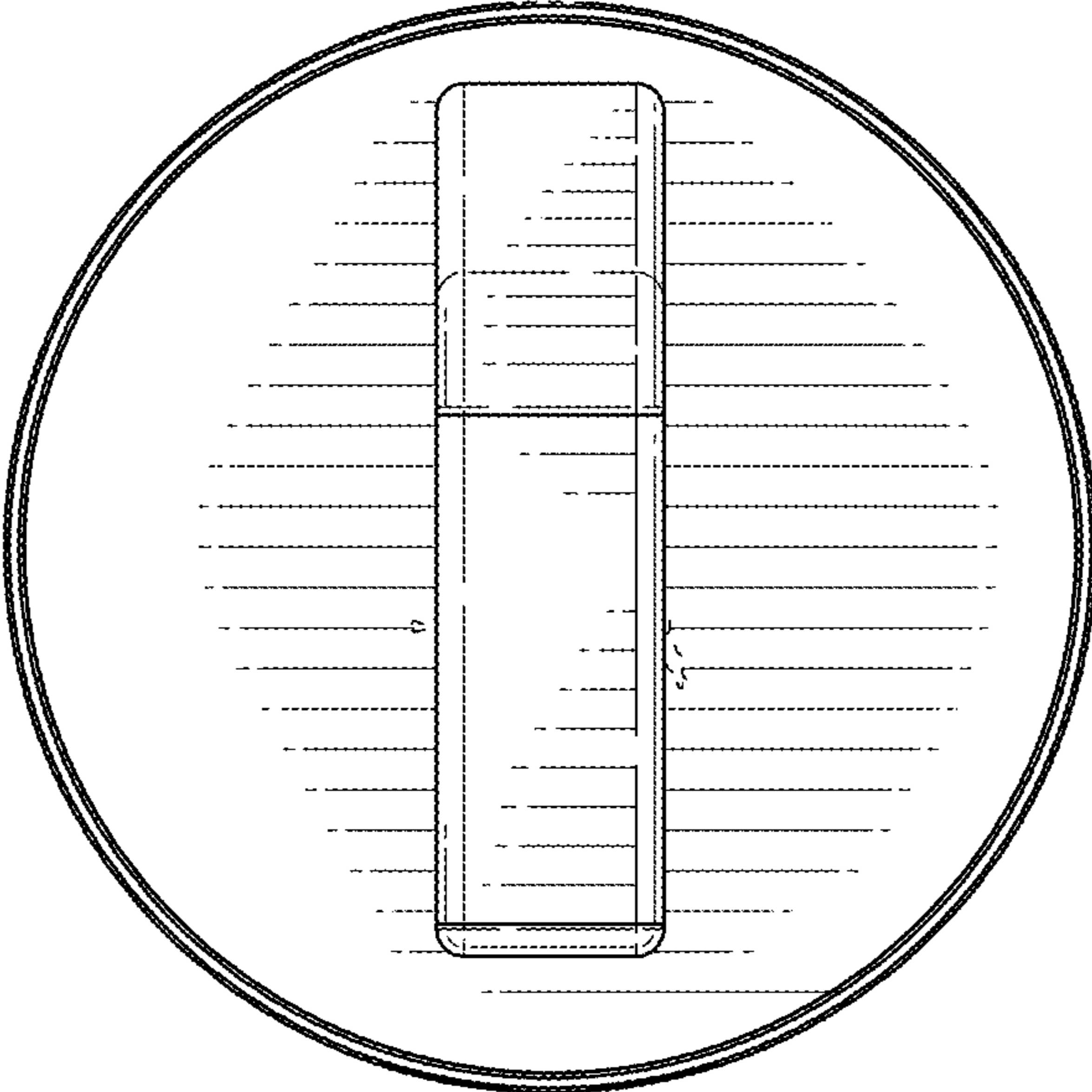


FIG. 34

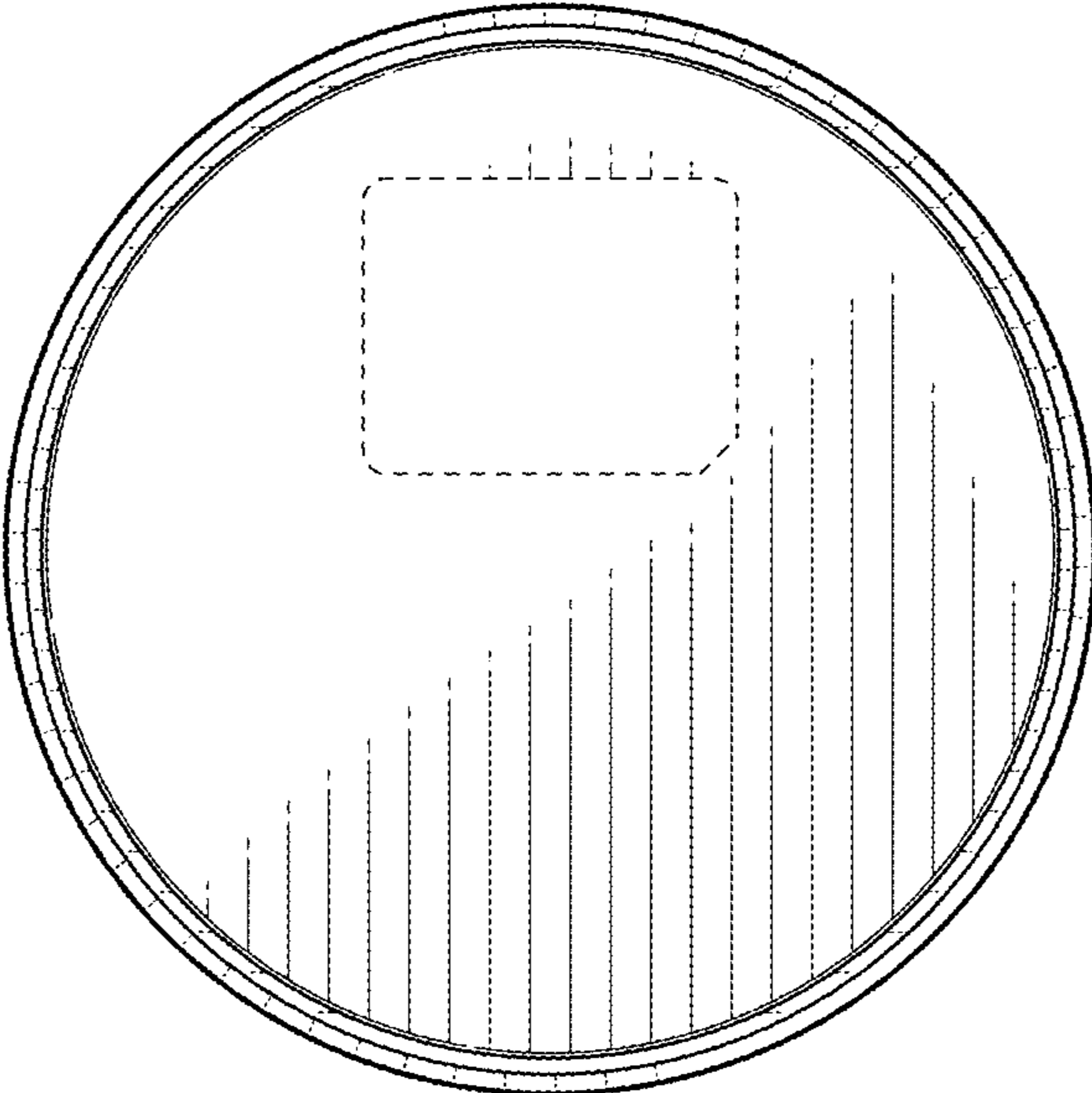


FIG. 35

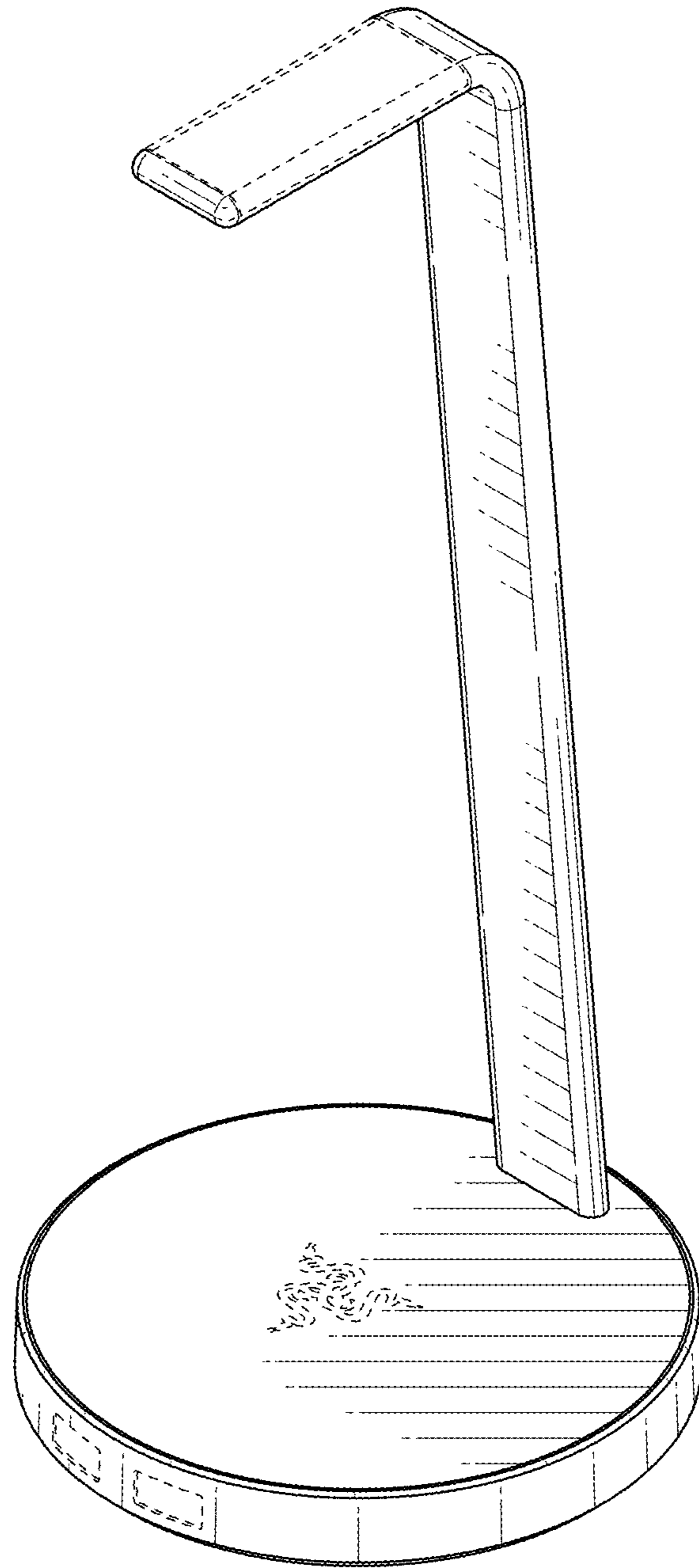


FIG. 36

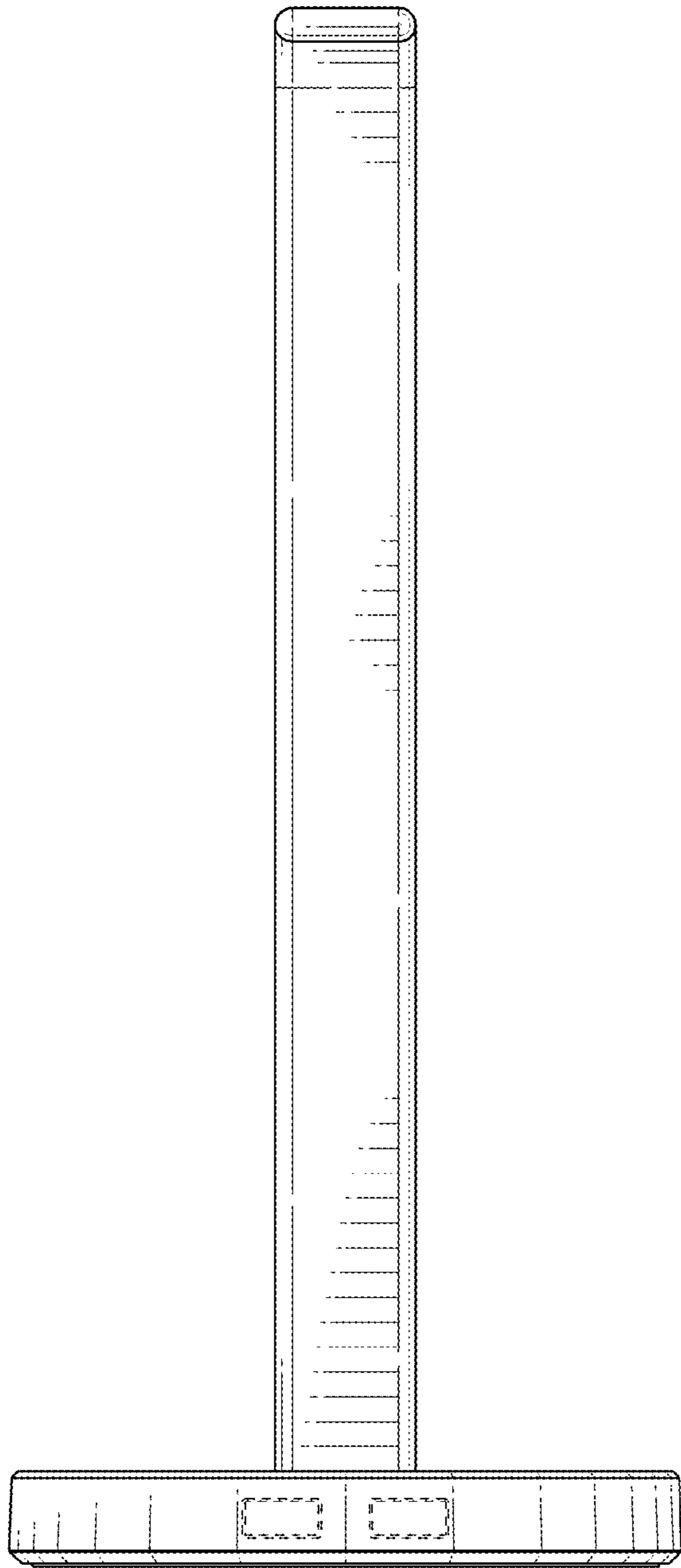


FIG. 37

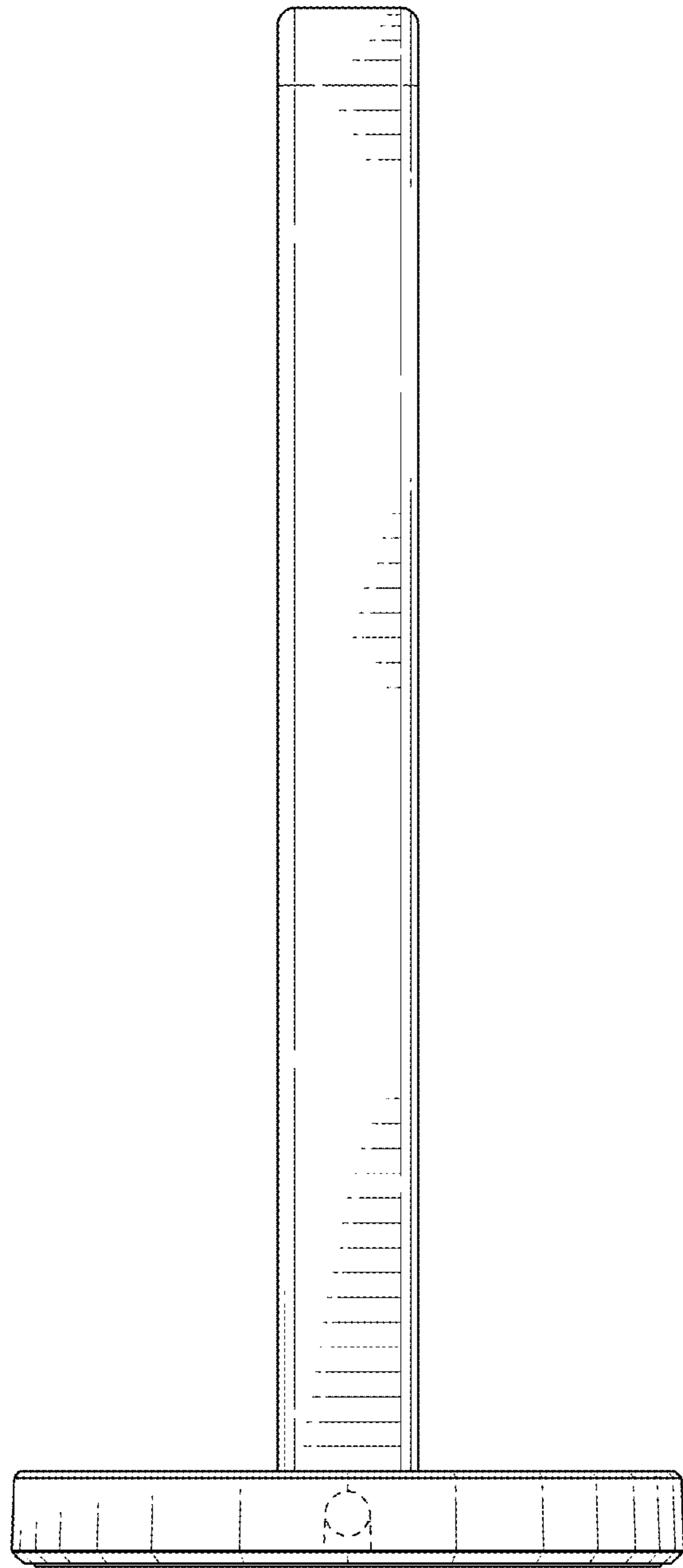


FIG. 38

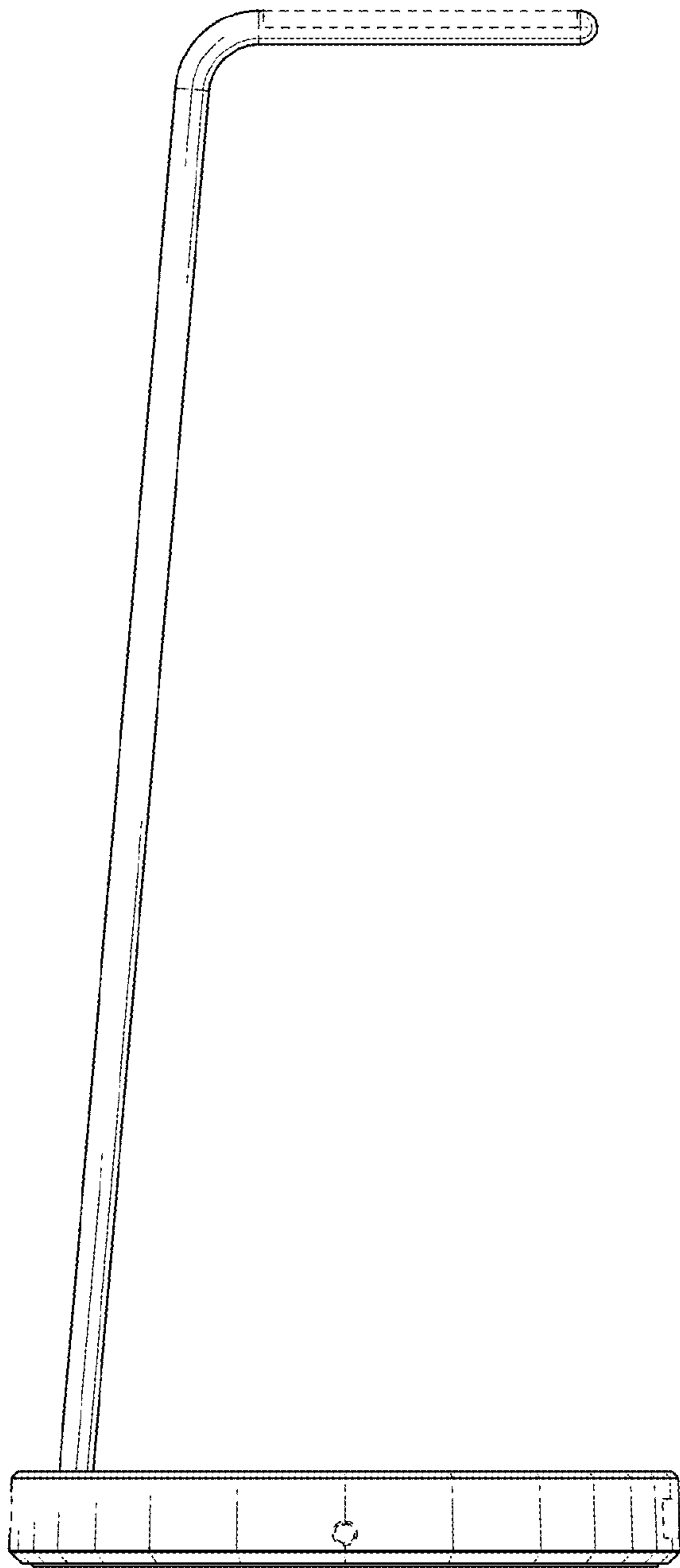


FIG. 39

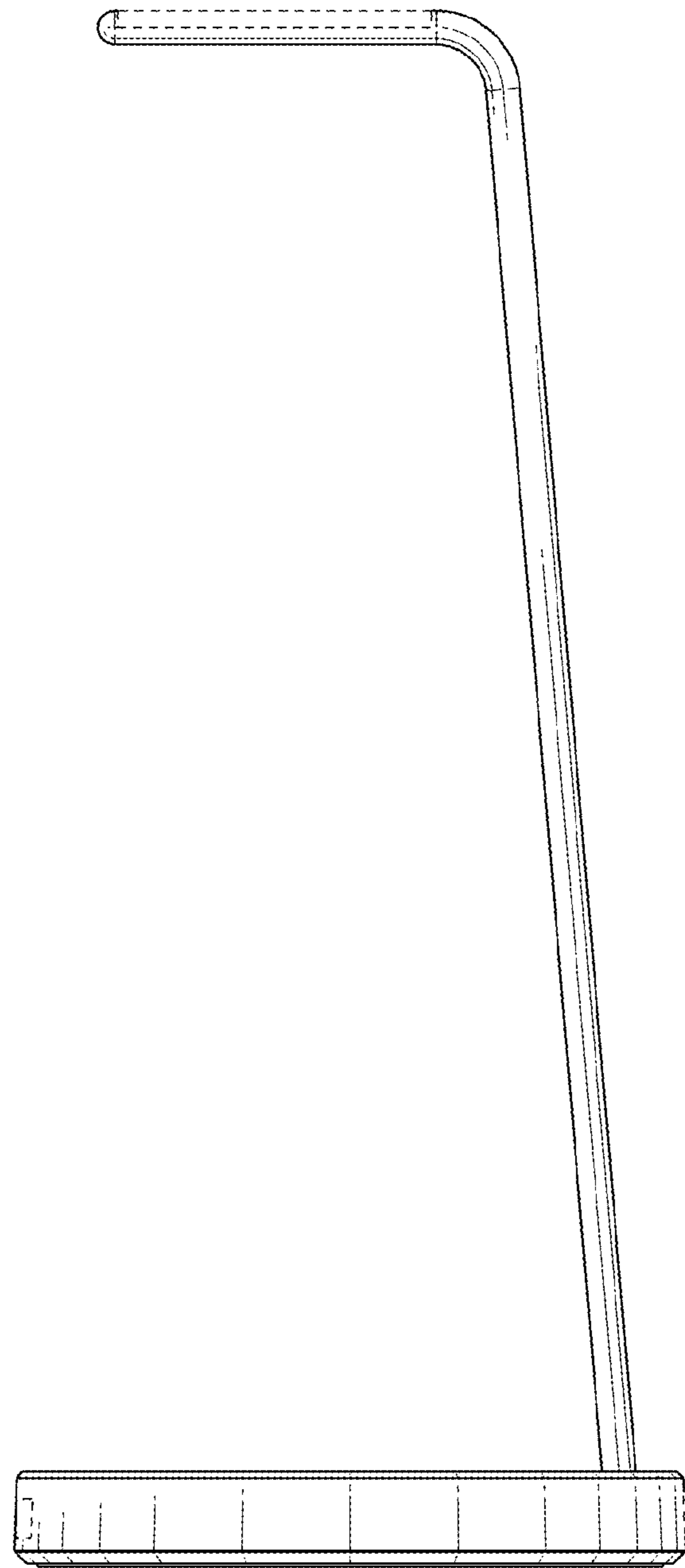


FIG. 40

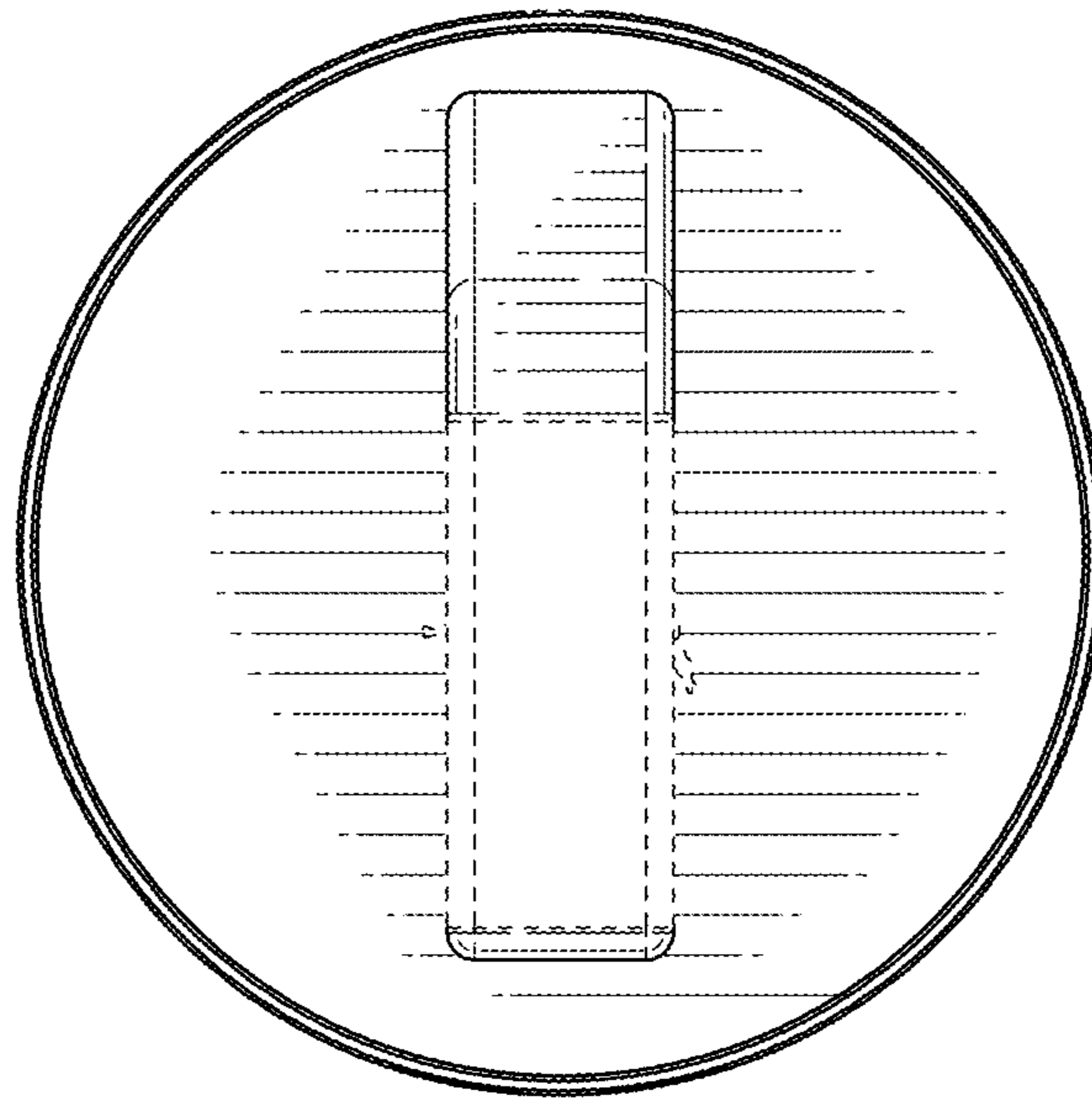


FIG. 41

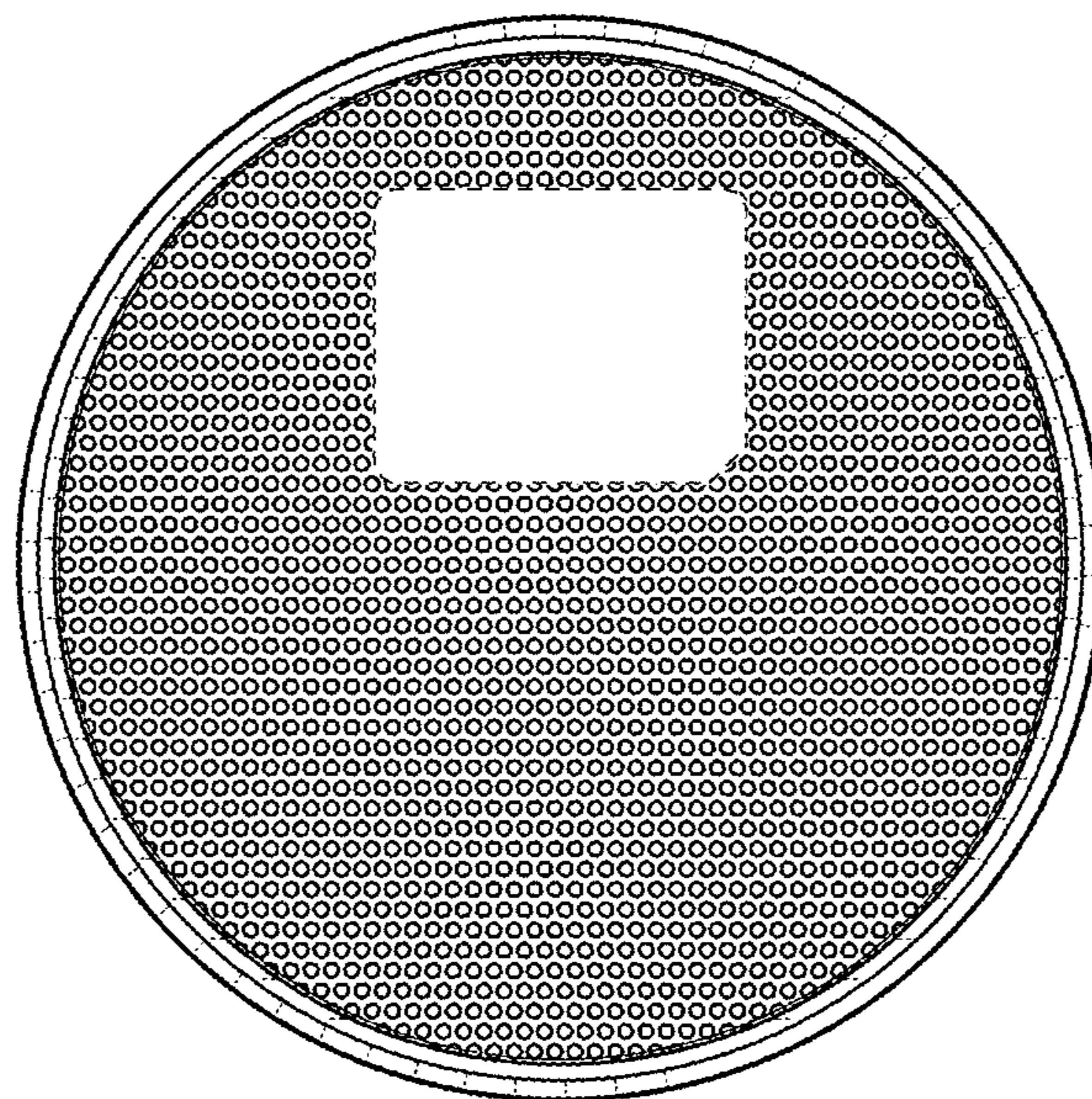


FIG. 42